

# 68HC05P9A

## SPECIFICATION (General Release)

© December 18, 1995

CSIC MCU Design Group  
Oak Hill, Texas



ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 1006

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**TABLE OF CONTENTS**

Section	Title	Page
<b>SECTION 1</b>		
<b>GENERAL DESCRIPTION</b>		
1.1	Features .....	1-1
1.2	Mask Options .....	1-2
1.3	MCU Structure .....	1-3
1.4	Pin Assignments .....	1-4
1.5	Signal Description .....	1-4
1.5.1	$V_{DD}$ and $V_{SS}$ .....	1-4
1.5.2	$\overline{IRQ}$ .....	1-4
1.5.3	$\overline{OSC1}$ and $\overline{OSC2}$ .....	1-5
1.5.4	$\overline{RESET}$ .....	1-5
1.5.5	TCMP .....	1-5
1.5.6	PA0 through PA7 .....	1-5
1.5.7	SDO/PB5, SDI/PB6, and SCK/PB7 .....	1-6
1.5.8	PC0 through PC7 .....	1-6
1.5.9	PD5 and TCAP/PD7 .....	1-6
1.6	Input/Output Programming .....	1-6
<b>SECTION 2</b>		
<b>MEMORY</b>		
2.1	ROM .....	2-3
2.2	ROM Security Feature .....	2-3
2.3	RAM .....	2-3
<b>SECTION 3</b>		
<b>CENTRAL PROCESSING UNIT</b>		
3.1	Accumulator (A) .....	3-1
3.2	Index Register (X) .....	3-1
3.3	Condition Code Register (CCR) .....	3-1
3.3.1	H — Half Carry .....	3-1
3.3.2	I — Interrupt .....	3-2
3.3.3	N — Negative .....	3-2
3.3.4	Z — Zero .....	3-2
3.3.5	C — Carry/Borrow .....	3-2
3.4	Stack Pointer (SP) .....	3-2
3.5	Program Counter (PC) .....	3-3

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**TABLE OF CONTENTS**

Section	Title	Page
<b>SECTION 4 INTERRUPTS</b>		
4.1	Hardware Controlled Interrupt Sequence .....	4-2
4.2	Timer Interrupt .....	4-3
4.3	External Interrupt .....	4-4
4.4	Optional External Interrupts (PA0-PA7) .....	4-6
4.5	Software Interrupt (SWI) .....	4-6
<b>SECTION 5 RESETS</b>		
5.1	Power-On Reset (POR) .....	5-1
5.2	$\overline{\text{RESET}}$ Pin .....	5-1
5.3	Computer Operating Properly (COP) Reset .....	5-1
<b>SECTION 6 LOW POWER MODES</b>		
6.1	STOP Instruction.....	6-1
6.2	Stop Mode .....	6-1
6.3	Halt Mode.....	6-2
6.2	WAIT Instruction.....	6-2
<b>SECTION 7 SIMPLE SERIAL INPUT/OUTPUT PORT</b>		
7.1	Signal Format .....	7-1
7.1.1	Serial Clock (SCK) .....	7-1
7.1.2	Serial Data Out (SDO) .....	7-2
7.1.3	Serial Data In (SDI) .....	7-2
7.2	SIOPI Registers .....	7-3
7.2.1	SIOPI Control Register (SCR) .....	7-3
7.2.2	SIOPI Status Register (SSR) .....	7-4
7.2.3	SIOPI Data Register (SDR) .....	7-5
<b>SECTION 8 TIMER</b>		
8.1	Counter .....	8-2
8.2	Output Compare Register .....	8-3
8.3	Input Capture Register .....	8-4
8.4	Timer Control Register (TCR) \$12 .....	8-5
8.5	Timer Status Register (TSR) \$13 .....	8-6

**TABLE OF CONTENTS**

<b>Section</b>	<b>Title</b>	<b>Page</b>
8.6	Timer During Wait Mode .....	8-7
8.7	Timer During Stop Mode .....	8-7

**SECTION 9  
COMPUTER OPERATING PROPERLY (COP)**

9.1	Resetting The COP .....	9-1
9.2	COP During Wait Mode .....	9-1
9.3	COP During Stop Mode .....	9-1

**SECTION 10  
ANALOG-TO-DIGITAL (A/D) CONVERTER**

10.1	Conversion Process .....	10-1
10.2	A/D Status and Control Register (ADSCR) .....	10-2
10.3	A/D Data Register (ADDR).....	10-3
10.4	A/D Converter During Wait Mode.....	10-4
10.5	A/D Converter During Stop or Halt Mode.....	10-4

**SECTION 11  
SELF-CHECK MODE**

**SECTION 12  
INSTRUCTION SET**

12.1	Addressing Modes .....	12-1
12.1.1	Inherent .....	12-1
12.1.2	Immediate .....	12-2
12.1.3	Direct .....	12-2
12.1.4	Extended .....	12-2
12.1.5	Indexed, No Offset .....	12-2
12.1.6	Indexed, 8-Bit Offset .....	12-2
12.1.7	Indexed, 16-Bit Offset .....	12-3
12.1.8	Relative .....	12-3
12.2	Instruction Types .....	12-4
12.2.1	Register/Memory Instructions .....	12-4
12.2.3	Read-Modify-Write Instructions .....	12-5
12.2.4	Jump/Branch Instructions .....	12-5
12.2.5	Bit Manipulation Instructions .....	12-7
12.2.6	Control Instructions .....	12-7
12.3	Instruction Set Summary .....	12-8

**TABLE OF CONTENTS**

<b>Section</b>	<b>Title</b>	<b>Page</b>
<b>SECTION 13</b>		
<b>ELECTRICAL SPECIFICATIONS</b>		
13.1	Maximum Ratings .....	13-1
13.2	Thermal Characteristics .....	13-1
13.3	DC Electrical Characteristics .....	13-2
13.4	A/D Converter Characteristics.....	13-4
13.4	SIOP Timing.....	13-5
13.5	Control Timing.....	13-6
<b>SECTION 14</b>		
<b>MECHANICAL SPECIFICATIONS</b>		
14.1	28-Pin Plastic Dual In-Line Package (Case 710-02) .....	14-1
14.2	28-Pin Small Outline Integrated Circuit Package (Case 751F-04) .....	14-2
<b>SECTION 15</b>		
<b>ORDERING INFORMATION</b>		
15.1	MCU Ordering Forms .....	15-1
15.2	Application Program Media .....	15-2
15.3	ROM Program Verification .....	15-3
15.4	ROM Verification Units (RVUs) .....	15-3

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**LIST OF FIGURES**

Figure	Title	Page
1-1	Block Diagram .....	1-3
1-2	Pin Assignments .....	1-4
1-3	Port A Pullup Option .....	1-5
1-4	I/O Circuitry .....	1-7
2-1	Memory Map .....	2-1
2-2	I/O Registers for the MC68HC05P9A .....	2-2
4-1	Hardware Interrupt Flowchart .....	4-3
4-2	IRQ Function Block Diagram .....	4-4
5-1	Power-On Reset and $\overline{\text{RESET}}$ .....	5-2
6-1	STOP/WAIT Flowcharts .....	6-3
7-1	SIOP Block Diagram .....	7-1
7-2	Serial I/O Port Timing .....	7-2
7-3	SIOP Control Register .....	7-3
7-4	SIOP Status Register .....	7-4
7-5	SIOP Data Register .....	7-5
8-1	Timer Block Diagram .....	8-2
8-2	Timer Control Register .....	8-5
8-3	Timer Status Register .....	8-6
10-1	A/D Status and Control Register (ADSCR).....	10-2
10-2	A/D Data Register (ADDR) .....	10-3
11-1	Self-Check Circuit .....	12-2
13-1	SIOP Timing Diagram .....	13-5
13-2	STOP Recovery Timing .....	13-7
13-3	External Interrupt Timing .....	13-7
13-4	Power-On Reset Timing .....	13-8
13-5	External Reset Timing .....	13-8

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**Freescale Semiconductor, Inc.**

GENERAL RELEASE SPECIFICATION

**Freescale Semiconductor, Inc.**

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006



**LIST OF TABLES**

<b>Table</b>	<b>Title</b>	<b>Page</b>
1-1	I/O Pin Functions .....	1-7
4-1	Vector Address for Interrupts and Reset .....	4-2
10-1	A/D Input Selection .....	10-3
11-1	Self-Check Results .....	11-1
12-1	Register/Memory Instructions .....	12-4
12-2	Read-Modify-Write Instructions .....	12-5
12-3	Jump and Branch Instructions .....	12-6
12-4	Bit Manipulation Instructions .....	12-7
12-5	Control Instructions .....	12-7
12-6	Instruction Set Summary .....	12-8
12-7	Opcode Map .....	12-14
13-1	DC Electrical Characteristics ( $V_{DD} = 5\text{ V}$ ) .....	13-2
13-2	DC Electrical Characteristics ( $V_{DD} = 3.3\text{ V}$ ) .....	13-3
13-3	A/D Converter Characteristics.....	13-4
13-4	SIOPI Timing ( $V_{DD} = 5\text{ V}$ ) .....	13-5
13-5	SIOPI Timing ( $V_{DD} = 3.3\text{ V}$ ) .....	13-5
13-6	Control Timing ( $V_{DD} = 5\text{ V}$ ) .....	13-6
13-7	Control Timing ( $V_{DD} = 3.3\text{ V}$ ) .....	13-6

Freescale Semiconductor, Inc.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**Freescale Semiconductor, Inc.**

GENERAL RELEASE SPECIFICATION

**Freescale Semiconductor, Inc.**

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

## SECTION 1 GENERAL DESCRIPTION

The MC68HC05P9A is a 28-pin device based on the MC68HC05P9. The memory map includes 2112 bytes of user ROM and 128 bytes of RAM. The MCU has two 8-bit input/output (I/O) ports, A and C. Port B has three I/O pins and port D has two pins, one that is I/O and the other input only. The MC68HC05P9A includes a four-channel 8-bit analog-to-digital (A/D) converter, a simple serial I/O peripheral (SIOP), and an on-chip mask programmable computer operating properly (COP) watchdog circuit.

### 1.1 Features

- Low Cost
- HC05 Core
- 28-Pin Package
- On-Chip Oscillator with RC or Crystal/Ceramic Resonator Mask Options
- 2112 Bytes of User ROM Including 16 User Vector Locations
- ROM Security Feature
- 128 Bytes of On-Chip RAM
- 16-Bit Timer
- 20 Bidirectional I/O Lines, One Input-Only Line
- Mask Programmable Keyscan (Pullups and Interrupt) on Eight Port Pins (PA0 through PA7)
- Two Port Pins with High Current Drive Capability (PC0, PC1)
- User Mode
- Four-Channel 8-Bit A/D Converter
- Self-Check Mode

- Power-Saving Stop and Wait Modes
- STOP Conversion to Halt Mode (Mask Option)
- Edge-Sensitive or Edge- and Level-Sensitive Interrupt Trigger Mask Option
- Simple Serial Input/Output Port
- Mask Option Selectable Watchdog Timer (COP)

### 1.2 Mask Options

There are 13 mask options on the MC68HC05P9A:

- CLOCK (RC or Crystal)
- $\overline{\text{IRQ}}$  (Edge-Sensitive Only or Edge- and Level-Sensitive)
- SIOP (MSB or LSB First)
- COP Watchdog Timer (Enable/Disable)
- Keyscan Pullups and Interrupts on Port A (Enable/Disable by Pin).
- Stop Instruction (Option to Convert to Halt)

All mask options and the user ROM are programmed on the 04E layer in fabrication.

---

#### NOTE

Negative true signals like  $\overline{\text{RESET}}$  and  $\overline{\text{IRQ}}$  will be denoted with an overline.

---

1.3 MCU Structure

Figure 1-1 shows the structure of the MC68HC05P9A.

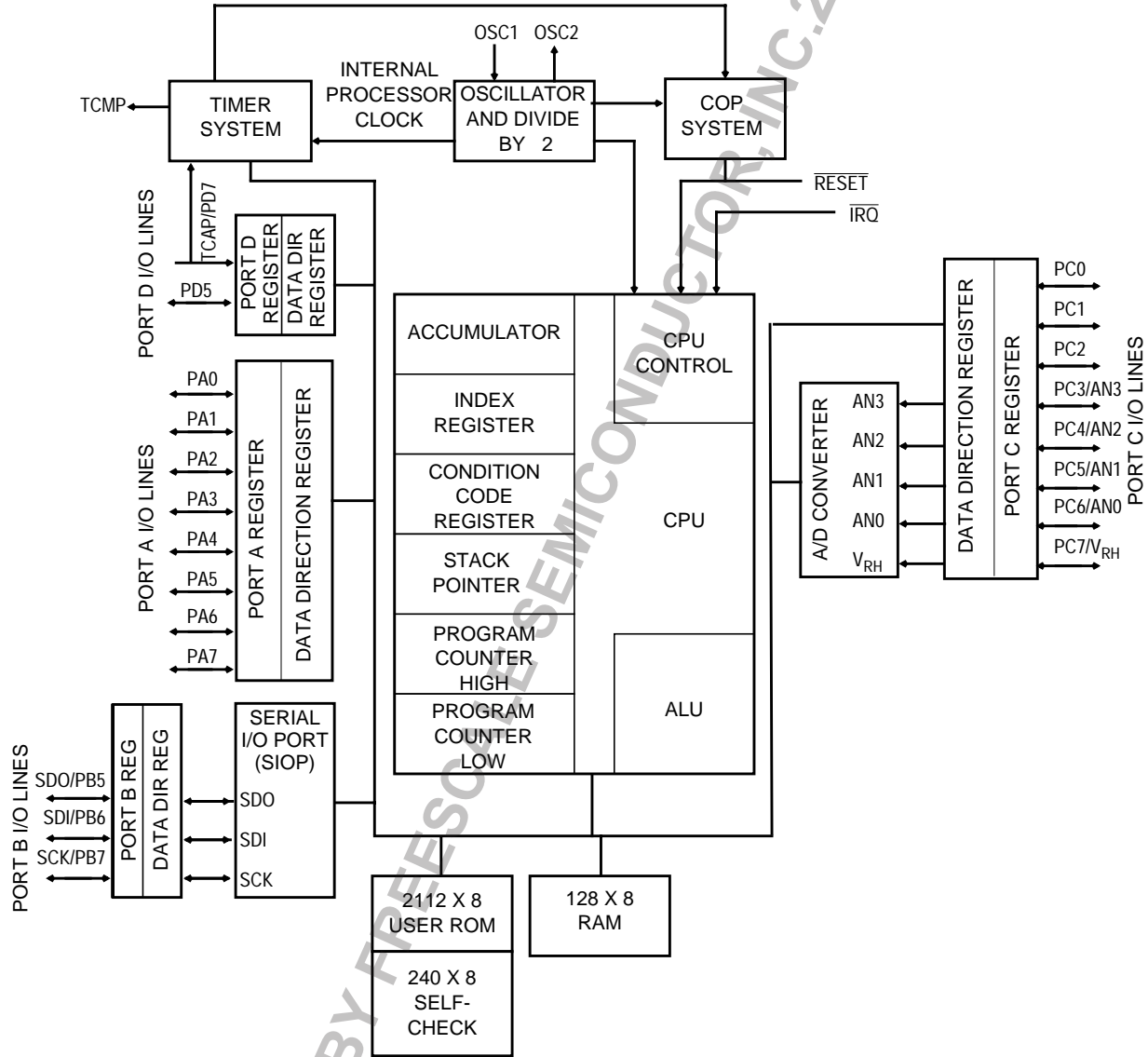
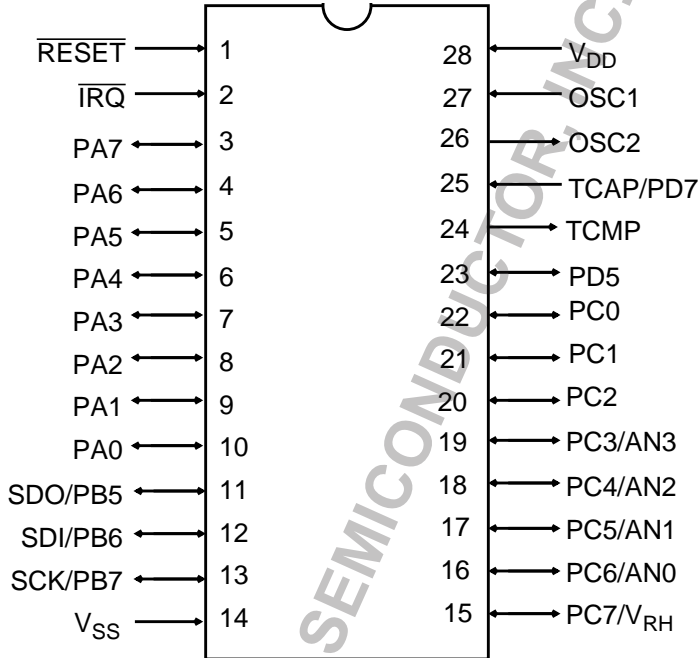


Figure 1-1. Block Diagram

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**1.4 Pin Assignments**

The MC68HC05P9A pin assignments are shown in Figure 1-2.



**Figure 1-2. Pin Assignments**

**1.5 Signal Description**

The following paragraphs provide a description of the signals.

**1.5.1 V<sub>DD</sub> and V<sub>SS</sub>**

Power is supplied to the microcontroller through V<sub>DD</sub> and V<sub>SS</sub>. V<sub>DD</sub> is the power supply and V<sub>SS</sub> is ground.

**1.5.2 IRQ**

This pin has a mask option that provides two different choices of interrupt triggering sensitivity. The IRQ pin contains an internal Schmitt trigger as part of its input to improve noise immunity. Refer to **SECTION 3 CENTRAL PROCESSING UNIT** for more detail.

1.5.3 OSC1 and OSC2

These pins provide control input for an on-chip clock oscillator circuit. A crystal, a ceramic resonator, a resistor/capacitor combination, or an external signal connects to these pins and provides a system clock. A mask option selects either a crystal/ceramic resonator or a resistor/capacitor as the frequency determining element. The oscillator frequency is two times the internal bus rate.

1.5.4 RESET

This active low pin is used to reset the MCU to a known start-up state by pulling RESET low. The RESET pin contains an internal Schmitt trigger as part of its input to improve noise immunity.

1.5.5 TCMP

This pin provides an output for the output compare feature of the on-chip timer system.

1.5.6 PA0 through PA7

Port A is an 8-bit bidirectional port which does not share any of its pins with other subsystems. The port A data register is at \$0000, and the data direction register is at \$0004. Reset does not affect the data registers, but clears the data direction registers, thereby returning the ports to inputs. Writing a one to a DDR bit sets the corresponding port bit to output mode. Port A has mask option enabled pullup devices and interrupt capability by pin. For a detailed description of I/O programming, refer to 1.6 Input/Output Programming.

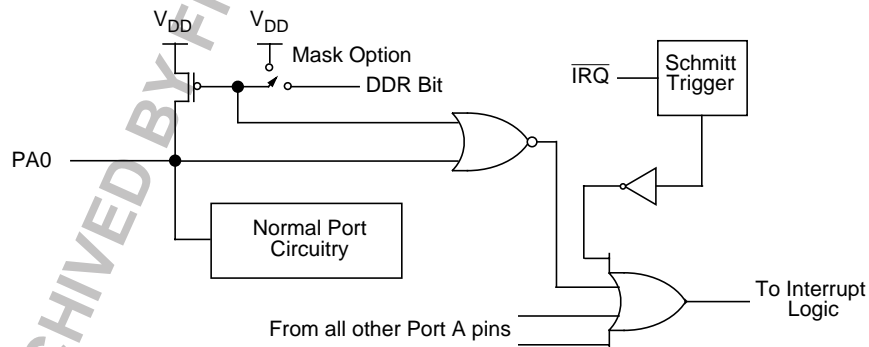


Figure 1-3. Port A Pullup Option

**1.5.7 SDO/PB5, SDI/PB6, and SCK/PB7**

Port B is a 3-bit bidirectional port. These pins are shared with the SIOP subsystem. Refer to **SECTION 7 SIMPLE SERIAL INPUT/OUTPUT PORT** for a detailed description of the SIOP. The address of the port B data register is \$0001 and the data direction register is at address \$0005. Reset does not affect the data registers, but clears the data direction registers, thereby returning the ports to inputs. Writing a one to a DDR bit sets the corresponding port bit to output mode.

**1.5.8 PC0 through PC2, PC3/AN3, PC4/AN2, PC5/AN1, PC6/AN0, PC7/V<sub>RH</sub>**

Port C, as an 8-bit shared function port, shares five of its pins with the A/D converter. When the A/D converter is not enabled, PC7–PC0 form an 8-bit general-purpose bidirectional I/O port. The contents of data direction register C (DDRC) determine whether each pin is an input or an output.

When the A/D converter is enabled, PC7 becomes V<sub>RH</sub>, and PC6–PC3 become AN0–AN3 (analog inputs 0–3). The values of CH1 and CH0 in the A/D status and control register (ADSCR) select one of the four pins as the input to the A/D converter. When the A/D converter is enabled a digital read of port C gives a logical zero from the selected analog input pin. A digital read of port C's remaining pins gives their correct digital values. V<sub>RH</sub> is the positive (high) reference voltage for the A/D converter. V<sub>SS</sub> is the negative (low) reference voltage. A reset turns off the A/D converter and configures port C as a general-purpose I/O port. See **SECTION 10 ANALOG-TO-DIGITAL (A/D) CONVERTER**.

The address of the port C data register is \$0002 and the data direction register is at address \$0006. Reset does not affect the data registers, but clears the data direction registers, thereby returning the ports to inputs. Writing a one to a DDR bit sets the corresponding port bit to output mode. Two of the port C pins, PC0 and PC1, have a higher current drive capability. See **SECTION 13 ELECTRICAL SPECIFICATIONS**.

**1.5.9 PD5 and TCAP/PD7**

Port D is a 2-bit port. PD5 is I/O and TCAP/PD7 is input-only shared with the timer input capture. The address of the port D data register is \$0003 and the data direction register is at address \$0007. Reset does not affect the data registers, but clears the data direction registers, thereby returning the ports to inputs. Writing a one to a DDR bit sets the corresponding port bit to output mode. The TCAP/PD7 pin controls the input capture feature for the on-chip programmable timer. This pin can be read at any time even if the TCAP function is enabled.



**1.6 Input/Output Programming**

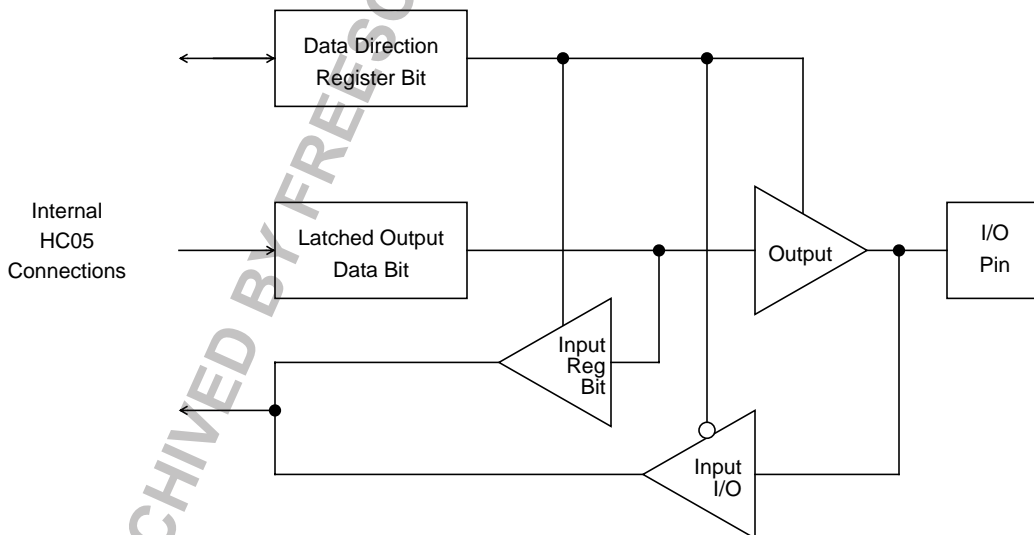
Port pins may be programmed as inputs or outputs under software control. The direction of the pins is determined by the state of the corresponding bit in the port data direction register (DDR). Each I/O port has an associated DDR. Any I/O port pin is configured as an output if its corresponding DDR bit is set to a logic one. A pin is configured as an input if its corresponding DDR bit is cleared to a logic zero.

At power-on or reset, all DDRs are cleared, which configures all pins as inputs. The data direction registers are capable of being written to or read by the processor. During the programmed output state, a read of the data register actually reads the value of the output data latch and not the I/O pin. For further information, see Table 1-1 and Figure 1-4.

**Table 1-1. I/O Pin Functions**

R/W	DDR	I/O Pin Function
0	0	The I/O pin is in input mode. Data is written into the output data latch.
0	1	Data is written into the output data latch and output to the I/O pin.
1	0	The state of the I/O pin is read.
1	1	The I/O pin is in an output mode. The output data latch is read.

R/W is an internal signal.



**Figure 1-4. I/O Circuitry**

**Freescale Semiconductor, Inc.**

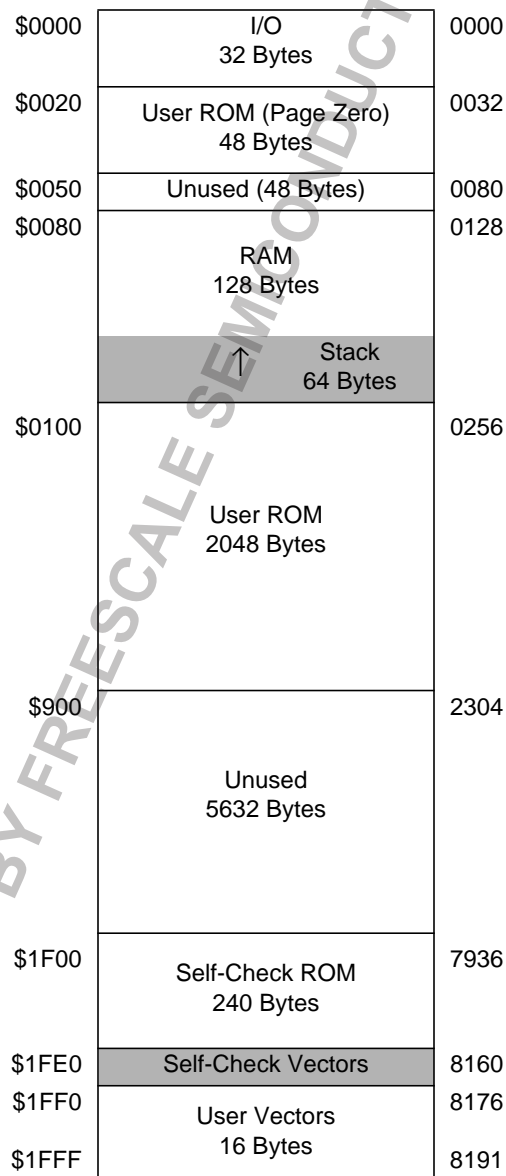
GENERAL RELEASE SPECIFICATION

**Freescale Semiconductor, Inc.**

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**SECTION 2  
MEMORY**

The MC68HC05P9A has an eight Kbyte memory map, consisting of user ROM, user RAM, self-check ROM, and I/O. See Figure 2-1 and Figure 2-2.



**Figure 2-1. Memory Map**

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

# Freescale Semiconductor, Inc.

## GENERAL RELEASE SPECIFICATION

ADDRESS \$0000 to \$001F	DATA							
	7	6	5	4	3	2	1	0
\$00 PORT A DATA								
\$01 PORT B DATA				0	0	0	0	0
\$02 PORT C DATA								
\$03 PORT D DATA		0		1	0	0	0	0
\$04 PORT A DDR								
\$05 PORT B DDR				1	1	1	1	1
\$06 PORT C DDR								
\$07 PORT D DDR	0	0		0	0	0	0	0
\$08 UNUSED								
\$09 UNUSED								
\$0A SERIAL CTRL	0	SPE	0	MSTR	0	0	0	0
\$0B SERIAL STAT	SPF	DCOL	0	0	0	0	0	0
\$0C SERIAL DATA								
\$0D UNUSED								
\$0E UNUSED								
\$0F UNUSED								
\$10 UNUSED								
\$11 UNUSED								
\$12 TIMER CONTROL	ICIE	OCIE	TOIE	0	0	0	IEDG	OLVL
\$13 TIMER STATUS	ICF	OCF	TOF	0	0	0	0	0
\$14 CAPTURE HIGH								
\$15 CAPTURE LOW								
\$16 COMPARE HIGH								
\$17 COMPARE LOW								
\$18 COUNTER HIGH								
\$19 COUNTER LOW								
\$1A DUAL TM HIGH								
\$1B DUAL TM LOW								
\$1C UNUSED								
\$1D ADDR								
\$1E ADSCR	CCF	ADRC	ADON	0	0	0	CH1	CH0
\$1F RESERVED								

Figure 2-2. I/O Registers for the MC68HC05P9A

MEMORY

MC68HC05P9A

**2.1 ROM**

The user ROM consists of 48 bytes of page zero ROM from \$0020 to \$004F, 2048 bytes of ROM from \$0100 to \$08FF, and 16 bytes of user vectors from \$1FF0 to \$1FFF. The self-check ROM and vectors are located from \$1F00 to \$1FEF.

**2.2 ROM Security Feature**

A security feature has been incorporated into the MC68HC05P9A to help prevent external reading of code in the ROM. Placing unique customer code at ROM locations \$0028-\$002F aids in keeping customer developed software proprietary.

**2.3 RAM**

The user RAM consists of 128 bytes of a shared stack area. The stack begins at address \$00FF. The stack pointer can access 64 bytes of RAM in the range \$00FF to \$00C0.

---

**NOTE**

Using the stack area for data storage or temporary work locations requires care to prevent it from being overwritten due to stacking from an interrupt or subroutine call.

---

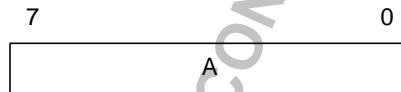
ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**SECTION 3  
CENTRAL PROCESSING UNIT**

This section describes the five CPU registers. CPU registers are not part of the memory map.

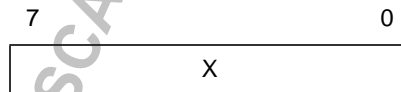
**3.1 Accumulator (A)**

The accumulator is a general purpose 8-bit register used to hold operands and results of arithmetic calculations or data manipulations.



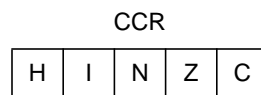
**3.2 Index Register (X)**

The index register is an 8-bit register used for the indexed addressing value to create an effective address. The index register also may be used as a temporary storage area.



**3.3 Condition Code Register (CCR)**

The CCR is a 5-bit register in which four bits are used to indicate the results of the instruction just executed, and the fifth bit indicates whether interrupts are masked. These bits can be tested individually by a program, and specific actions can be taken as a result of their state. Each bit is explained in the following paragraphs.



**3.3.1 H — Half Carry**

This bit is set during ADD and ADC operations to indicate that a carry occurred between bits 3 and 4.

**3.3.2 I — Interrupt**

When this bit is set, timer and external interrupts are masked (disabled). If an interrupt occurs while this bit is set, the interrupt is latched and processed as soon as the interrupt bit is cleared.

**3.3.3 N — Negative**

When set, this bit indicates that the result of the last arithmetic, logical, or data manipulation was negative.

**3.3.4 Z — Zero**

When set, this bit indicates that the result of the last arithmetic, logical, or data manipulation was zero.

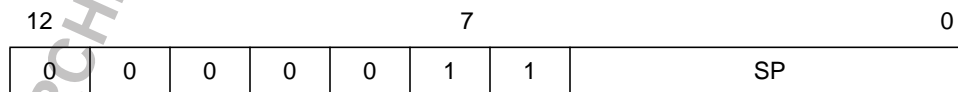
**3.3.5 C — Carry/Borrow**

When set, this bit indicates that a carry or borrow out of the arithmetic logical unit (ALU) occurred during the last arithmetic operation. This bit is also affected during bit test and branch instructions and during shifts and rotates.

**3.4 Stack Pointer (SP)**

The stack pointer contains the address of the next free location on the stack. During an MCU reset or the reset stack pointer (RSP) instruction, the stack pointer is set to location \$00FF. The stack pointer is then decremented as data is pushed onto the stack and incremented as data is pulled from the stack.

When accessing memory, the seven most significant bits are permanently set to 000011. These seven bits are appended to the six least significant register bits to produce an address within the range of \$00FF to \$00C0. Subroutines and interrupts may use up to 64 (decimal) locations. If 64 locations are exceeded, the stack pointer wraps around and loses the previously stored information. A subroutine call occupies two locations on the stack; an interrupt uses five locations.

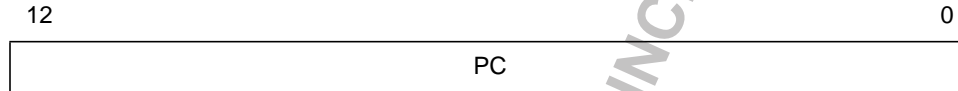


Freescale Semiconductor, Inc.



**3.5 Program Counter (PC)**

The program counter is a 13-bit register that contains the address of the next byte to be fetched.



---

**NOTE**

The HC05 CPU core is capable of addressing a 64 Kbyte memory map. For this implementation, however, the addressing registers are limited to an 8 Kbyte memory map.

---

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**Freescale Semiconductor, Inc.**

GENERAL RELEASE SPECIFICATION

**Freescale Semiconductor, Inc.**

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

## SECTION 4 INTERRUPTS

The MCU can be interrupted four different ways: the two maskable hardware interrupts ( $\overline{\text{IRQ}}$  and timer), the non-maskable software interrupt instruction (SWI), and by the optional external asynchronous interrupt on each port A pin (enabled by pullup mask option).

Interrupts cause the processor to save register contents on the stack and to set the interrupt mask (I bit) to prevent additional interrupts. The RTI instruction causes the register contents to be recovered from the stack and normal processing to resume.

Unlike  $\overline{\text{RESET}}$ , hardware interrupts do not cause the current instruction execution to be halted, but are considered pending until the current instruction is complete.

---

### NOTE

The current instruction is the one already fetched and being operated on.

---

When the current instruction is complete, the processor checks all pending hardware interrupts. If interrupts are not masked (CCR I bit clear) and if the corresponding interrupt enable bit is set, the processor proceeds with interrupt processing; otherwise, the next instruction is fetched and executed.

If both an external interrupt and a timer interrupt are pending at the end of an instruction execution, the external interrupt is serviced first. The SWI is executed the same as any other instruction, regardless of the I-bit state.

Table 4-1 lists vector addresses for all interrupts including reset.

**Table 4-1. Vector Address for Interrupts and Reset**

Register	Flag Name	Interrupts	CPU Interrupt	Vector Address
N/A	N/A	Reset	$\overline{\text{RESET}}$	\$1FFE-\$1FFF
N/A	N/A	Software	SWI	\$1FFC-\$1FFD
N/A	N/A	External Interrupt	$\overline{\text{IRQ}}$	\$1FFA-\$1FFB
TSR	ICF	Timer Input Capture	TIMER	\$1FF8-\$1FF9
TSR	OCF	Timer Output Capture	TIMER	\$1FF8-\$1FF9
TSR	TOF	Timer Overflow	TIMER	\$1FF8-\$1FF9

**4.1 Hardware Controlled Interrupt Sequence**

The following three functions ( $\overline{\text{RESET}}$ , STOP, and WAIT) are not interrupts in the strictest sense. However, they are acted upon in a similar manner. Flowcharts for hardware interrupts are shown in Figure 4-1, and for STOP and WAIT in Figure 6-1. A discussion is provided below.

1.  $\overline{\text{RESET}}$  — A low input on the  $\overline{\text{RESET}}$  input pin causes the program to vector to its starting address, which is specified by the contents of memory locations \$1FFE and \$1FFF. The I bit in the condition code register also is set. Much of the MCU is configured to a known state during this type of reset as described in **SECTION 5 RESETS**.
2. STOP — The STOP instruction causes the oscillator to be turned off and the processor to "sleep" until an external interrupt ( $\overline{\text{IRQ}}$ ) or reset occurs. See **6.1.1 Stop Mode**.
3. WAIT or HALT — The WAIT or HALT instruction causes all processor clocks to stop, but leaves the timer clock running. This rest state of the processor can be cleared by reset, an external interrupt ( $\overline{\text{IRQ}}$ ), or timer interrupt. These individual interrupts have no special wait vectors. See **6.1.2 Halt Mode**.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2008

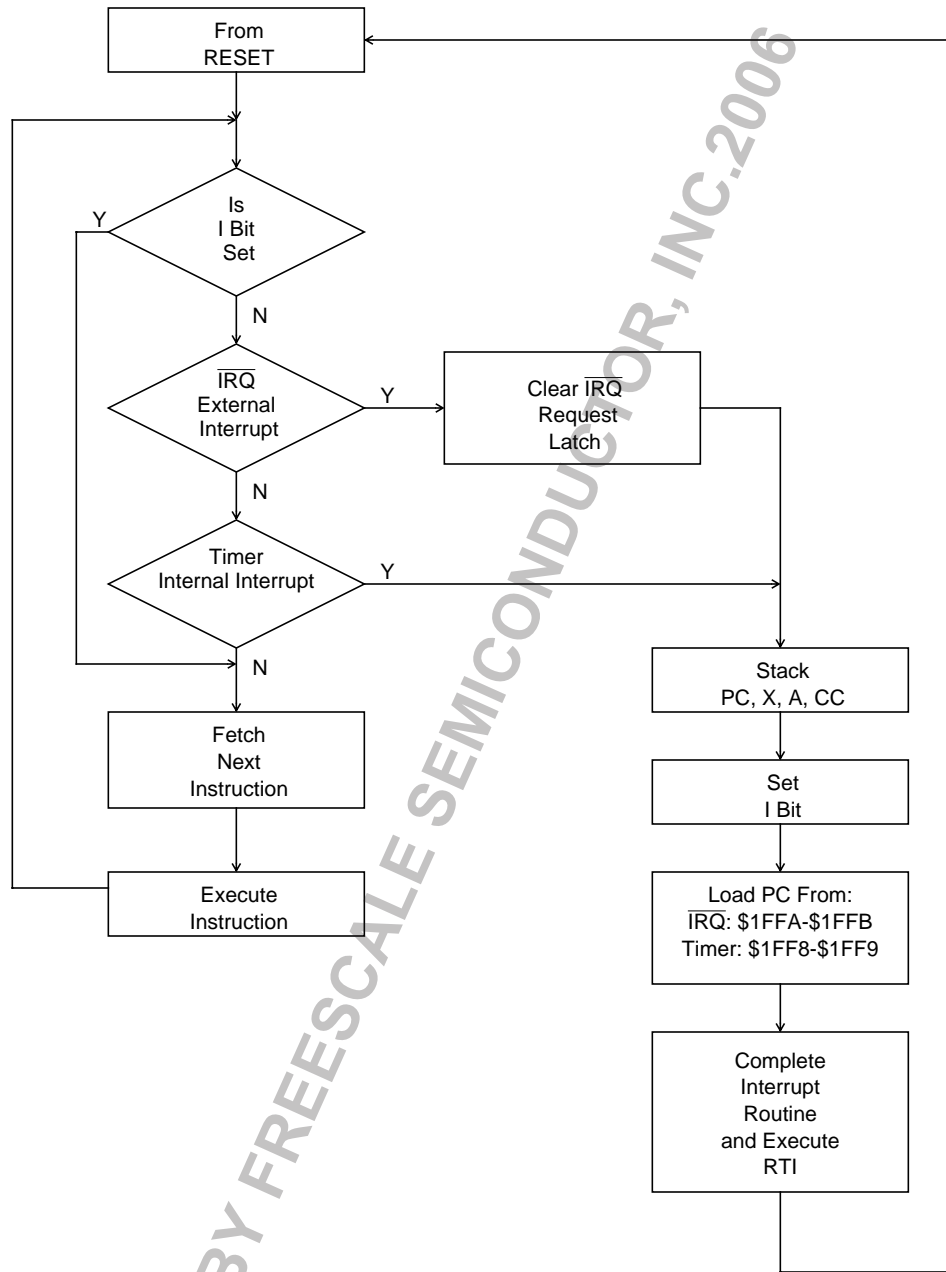


Figure 4-1. Hardware Interrupt Flowchart

#### 4.2 Timer Interrupt

Three different timer interrupt flags cause a timer interrupt when they are set and enabled. The interrupt flags are in the timer status register (TSR), and the enable bits are in the timer control register (TCR). Any of these interrupts will vector to the same interrupt service routine, located at the address specified by the contents of memory location \$1FF8 and \$1FF9.

### 4.3 External Interrupt

The  $\overline{\text{IRQ}}$  pin drives an asynchronous interrupt to the CPU. An edge detector flip-flop is latched on the falling edge of  $\overline{\text{IRQ}}$ . If either the output from the internal edge detector flip-flops or the level on the  $\overline{\text{IRQ}}$  pin is low, a request is synchronized to the CPU to generate the IRQ interrupt. If the edge-sensitive only mask option is selected, the output of the internal edge detector flip-flop is sampled and the input level on the  $\overline{\text{IRQ}}$  pin is ignored. The interrupt service routine address is specified by the contents of memory locations \$1FFA and \$1FFB. A block diagram of the IRQ function is shown in Figure 4-2.

NOTE

The internal interrupt latch is cleared nine PH2 clock cycles after the interrupt is recognized (after location \$1FFA is read). Therefore, another external interrupt pulse can be latched during the IRQ service routine.

NOTE

When the edge- and level-sensitive mask option is selected, the voltage applied to the  $\overline{\text{IRQ}}$  pin must return to the high state before the RTI instruction in the interrupt service routine is executed to avoid the processor re-entering the IRQ service routine.

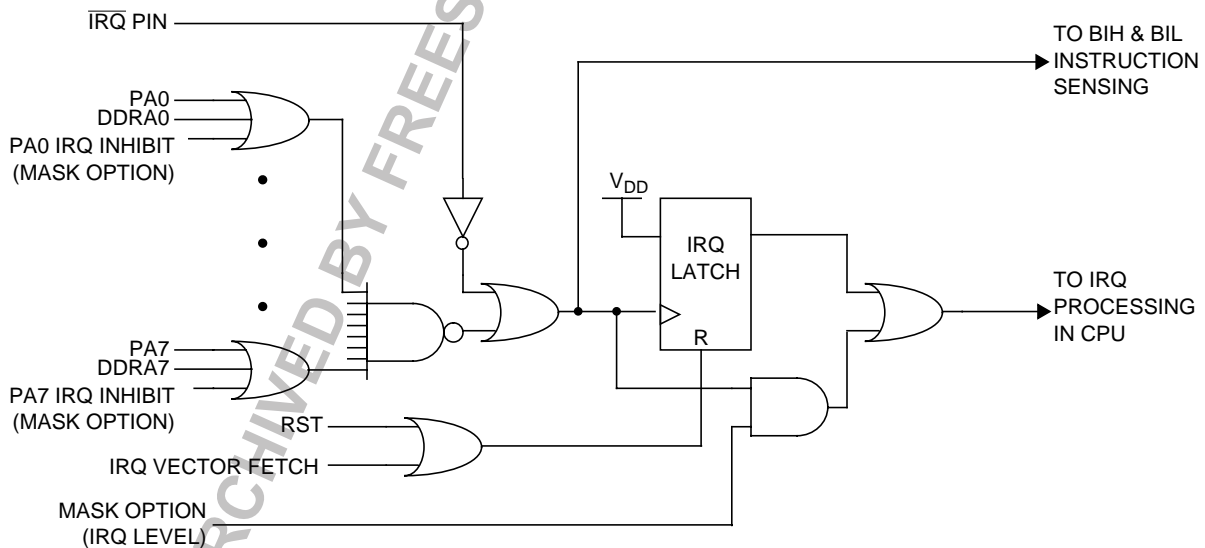


Figure 4-2. IRQ Function Block Diagram

The  $\overline{\text{IRQ}}$  pin is one source of an IRQ interrupt and a mask option can also enable the port A pins (PA0 thru PA7) to act as other IRQ interrupt sources. These sources are all combined into a single ORing function to be latched by the IRQ latch.

Any enabled IRQ interrupt source sets the IRQ latch on the falling edge of the  $\overline{\text{IRQ}}$  pin or a port A pin if port A interrupts have been enabled. If edge-only sensitivity is chosen by a mask option, only the IRQ latch output can activate a request to the CPU to generate the IRQ interrupt sequence. This makes the IRQ interrupt sensitive to the following cases:

1. Falling edge on the  $\overline{\text{IRQ}}$  pin with all enabled port A interrupt pins at a high level.
2. Falling edge on any enabled port A interrupt pin with all other enabled port A interrupt pins and the  $\overline{\text{IRQ}}$  pin at a high level.

If level sensitivity is chosen, the active high state of the IRQ input can also activate an IRQ request to the CPU to generate the IRQ interrupt sequence. This makes the IRQ interrupt sensitive to the following cases:

1. Low level on the  $\overline{\text{IRQ}}$  pin.
2. Falling edge on the  $\overline{\text{IRQ}}$  pin with all enabled port A interrupt pins at a high level.
3. Low level on any enabled port A interrupt pin.
4. Falling edge on any enabled port A interrupt pin with all enabled port A interrupt pins on the  $\overline{\text{IRQ}}$  pin at a high level.

This interrupt is serviced by the interrupt service routine located at the address specified by the contents of \$1FFA and \$1FFB. The IRQ latch is automatically cleared by entering the interrupt service routine.

#### 4.4 Optional External Interrupts (PA0-PA7)

The IRQ interrupt can be triggered by the inputs on the PA0 thru PA7 port pins if enabled by individual mask options. With pullup enabled, each port A pin can activate the IRQ interrupt function and the interrupt operation will be the same as for inputs to the  $\overline{\text{IRQ}}$  pin. Once enabled by mask option, each individual port A pin can be disabled as an interrupt source if its corresponding DDR bit is configured for output mode.

---

**NOTE**

The BIH and BIL instructions apply to the output of the logic OR function of the enabled PA0 thru PA7 interrupt pins and the  $\overline{\text{IRQ}}$  pin. The BIH and BIL instructions do not exclusively test the state of the  $\overline{\text{IRQ}}$  pin.

---

---

**NOTE**

If enabled, the PA0 thru PA7 pins will cause an IRQ interrupt only if these individual pins are configured as inputs.

---

#### 4.5 Software Interrupt (SWI)

The SWI is an executable instruction and a non-maskable interrupt. It is executed regardless of the state of the I bit in the CCR. If the I bit is zero (interrupts enabled), SWI executes after interrupts which were pending when the SWI was fetched but before interrupts generated after the SWI was fetched. The interrupt service routine address is specified by the contents of memory locations \$1FFC and \$1FFD.



## SECTION 5 RESETS

The MCU can be reset three ways: by the initial power-on reset function, by an active low input to the  $\overline{\text{RESET}}$  pin, and by a computer operating properly (COP) watchdog-timer timeout.

### 5.1 Power-On Reset (POR)

An internal reset is generated on power-up to allow the internal clock generator to stabilize. The power-on reset is strictly for power turn-on conditions and should not be used to detect a drop in the power supply voltage.

There is a 4064 internal processor clock cycle ( $t_{\text{cyc}}$ ) oscillator stabilization delay after the oscillator becomes active. If the  $\overline{\text{RESET}}$  pin is low at the end of this 4064-cycle delay, the MCU will remain in the reset condition until  $\overline{\text{RESET}}$  goes high.

### 5.2 $\overline{\text{RESET}}$ Pin

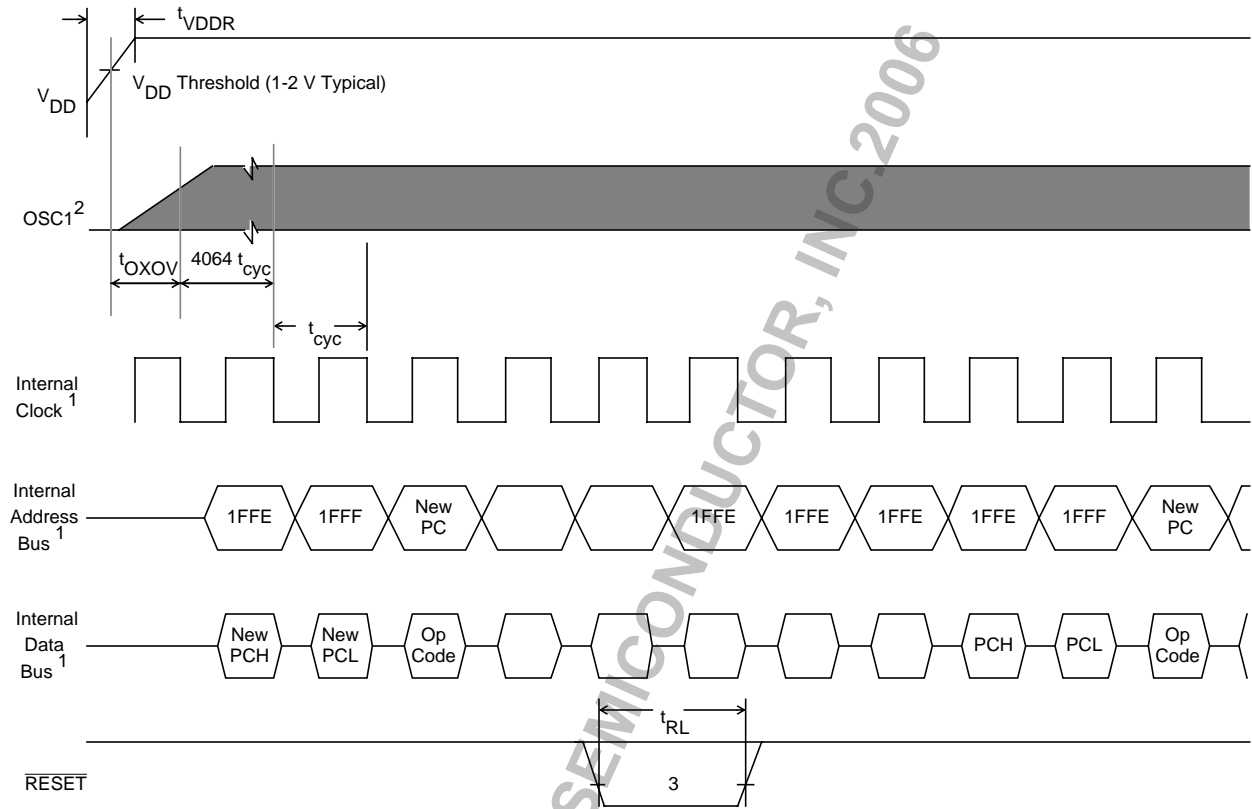
The MCU is reset when a logic zero is applied to the  $\overline{\text{RESET}}$  input for a period of one and one-half machine cycles ( $t_{\text{cyc}}$ ).

### 5.3 Computer Operating Properly (COP) Reset

The MCU contains a watchdog timer that automatically times out if not reset (cleared) within a specific time by a program reset sequence. If the COP watchdog timer is allowed to time-out, an internal reset is generated to reset the MCU. Because the internal  $\overline{\text{RESET}}$  signal is used, the MCU comes out of a COP reset in the same operating mode it was in when the COP time-out was generated.

The COP reset function is enabled or disabled by a mask option.

Refer to **SECTION 9 COMPUTER OPERATING PROPERLY (COP)** for more information on the COP.



NOTES:

1. Internal timing signal and bus information not available externally.
2.  $OSC1$  line is not meant to represent frequency. It is only used to represent time.
3. The next rising edge of the internal processor clock following the rising edge of  $\overline{RESET}$  initiates the reset sequence.

Figure 5-1. Power-On Reset and  $\overline{RESET}$

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

## SECTION 6

### LOW POWER MODES

The MC68HC05P9A is capable of running in a low-power mode in each of its configurations. The WAIT and STOP instructions provide two modes that reduce the power required for the MCU by stopping various internal clocks and/or the on-chip oscillator. The STOP and WAIT instructions are not normally used if the COP watchdog timer is enabled. The stop conversion mask option is used to modify the behavior of the STOP instruction from stop mode to halt mode. The flow of the stop, halt, and wait modes is shown in Figure 6-1.

#### 6.1 STOP Instruction

The STOP instruction can result in one of two modes of operation, depending on the stop conversion mask option. If the stop conversion is not chosen, the STOP instruction will behave like a normal STOP instruction in the MC68HC05 Family and place the MCU in the stop mode. If the stop conversion is chosen, the STOP instruction will behave like a WAIT instruction (with the exception of a variable delay at startup) and place the MCU in the halt mode.

##### 6.1.1 Stop Mode

Execution of the STOP instruction without conversion to halt places the MCU in its lowest power consumption mode. In the stop mode the internal oscillator is turned off, halting *all* internal processing, including the COP watchdog timer. Execution of the STOP instruction automatically clears the I bit in the condition code register so that the  $\overline{\text{IRQ}}$  external interrupt is enabled. All other registers and memory remain unaltered. All input/output lines remain unchanged.

The MCU can be brought out of the stop mode only by an  $\overline{\text{IRQ}}$  external interrupt or an externally generated RESET. When exiting the stop mode, the internal oscillator will resume after a 4064 PH2 clock cycle oscillator stabilization delay.

---

#### NOTE

Execution of the STOP instruction without conversion to halt (via mask option) will cause the oscillator to stop, and therefore disable the COP watchdog timer. If the COP watchdog timer is used, the stop mode should be changed to the halt mode by selecting the appropriate mask option.

---

### 6.1.2 Halt Mode

Execution of the STOP instruction with the conversion to halt places the MCU in this low-power mode. Halt mode consumes the same amount of power as wait mode. (Both halt and wait modes consume more power than stop mode.)

In halt mode the PH2 clock is halted, suspending all processor and internal bus activity. Internal timer clocks remain active, permitting interrupts to be generated from the 16-bit timer or a reset to be generated from the COP watchdog timer. Execution of the STOP instruction automatically clears the I bit in the condition code register enabling the  $\overline{\text{IRQ}}$  external interrupt. All other registers, memory, and input/output lines remain in their previous states.

If the 16-bit timer interrupt is enabled, the processor will exit the halt mode and resume normal operation. The halt mode can also be exited when an  $\overline{\text{IRQ}}$  external interrupt or external  $\overline{\text{RESET}}$  occurs. When exiting the halt mode, the PH2 clock will resume after a delay of one to 4064 PH2 clock cycles. This varied delay time is the result of the halt mode exit circuitry testing the oscillator stabilization delay timer (a feature of the stop mode), which has been free-running (a feature of the wait mode).

---

#### NOTE

The halt mode is not intended for normal use. This feature is provided to keep the COP watchdog timer active in the event a STOP instruction is inadvertently executed.

---

### 6.2 WAIT Instruction

The WAIT instruction places the MCU in a low-power mode, which consumes more power than the stop mode. In wait mode, the PH2 clock is halted, suspending all processor and internal bus activity. Internal timer clocks remain active, permitting interrupts to be generated from the 16-bit timer and reset to be generated from the COP watchdog timer. Execution of the WAIT instruction automatically clears the I bit in the condition code register enabling the  $\overline{\text{IRQ}}$  external interrupt. All other registers, memory, and input/output lines remain in their previous state.

If the 16-bit timer interrupt is enabled, it will cause the processor to exit the wait mode and resume normal operation. The 16-bit timer may be used to generate a periodic exit from the wait mode. The wait mode may also be exited when an  $\overline{\text{IRQ}}$  external interrupt or  $\overline{\text{RESET}}$  occurs.

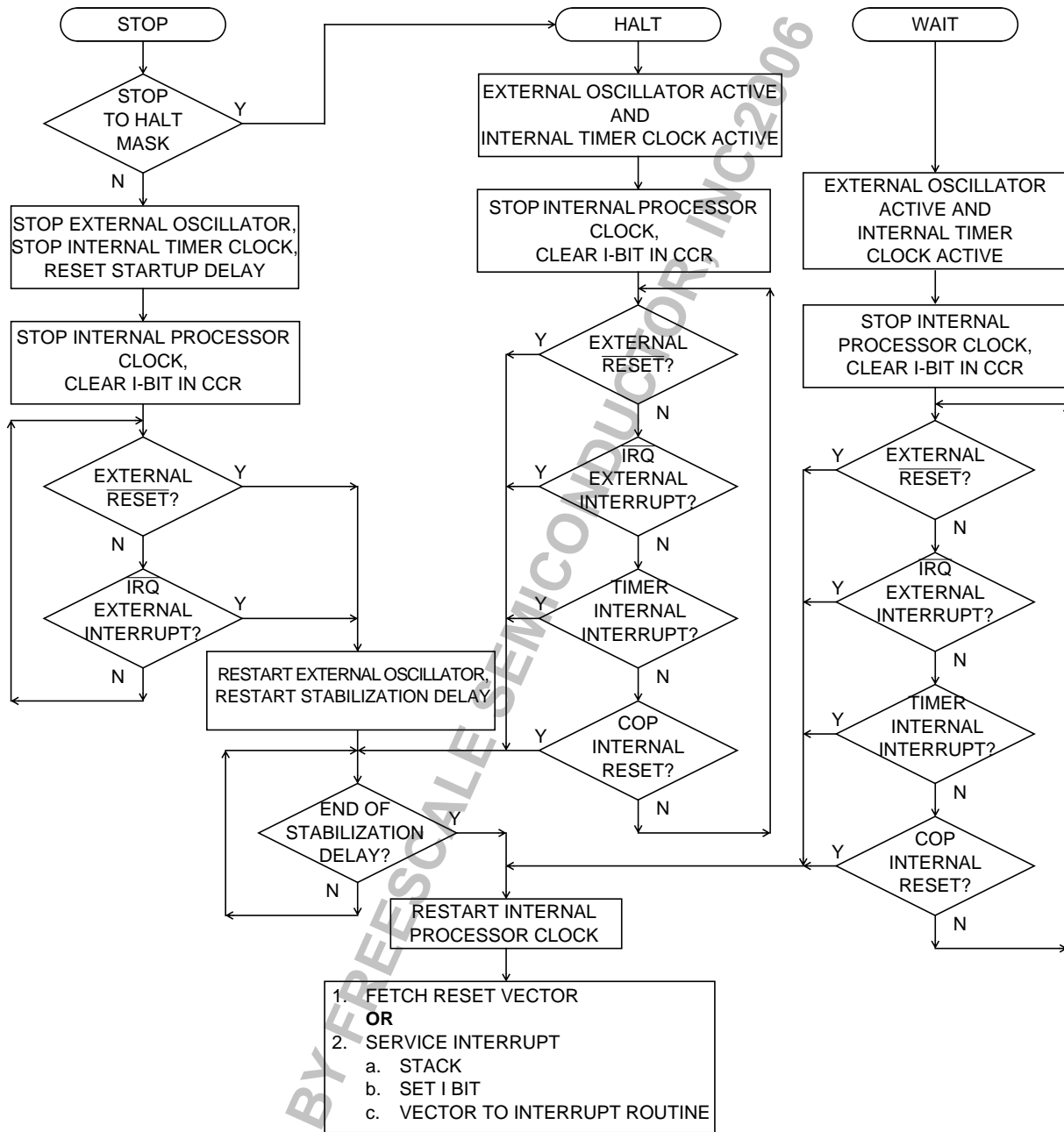


Figure 6-1. STOP/WAIT Flowcharts

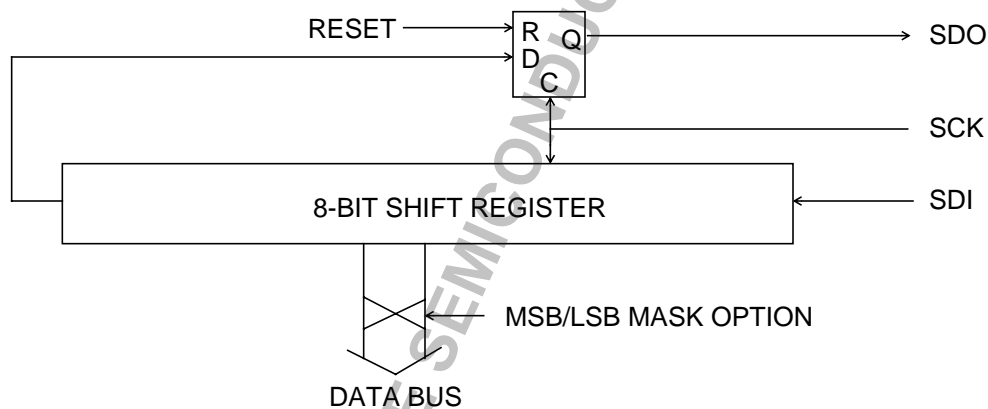
Freescale Semiconductor, Inc.

ARCHIVED BY FREESCALE SEMICONDUCTOR INC 2006

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**SECTION 7  
SIMPLE SERIAL INPUT/OUTPUT PORT**

This device includes a simple synchronous serial I/O port. The SIOP is a three wire master/slave system including serial clock (SCK), serial data input (SDI), and serial data output (SDO). A mask programmable option determines whether the SIOP is MSB or LSB first.



**Figure 7-1. SIOP Block Diagram**

**7.1 Signal Format**

The following paragraphs describe the SIOP signal format.

**7.1.1 Serial Clock (SCK)**

The state of SCK between transmissions and prior to enabling the SIOP must be logic one. The first falling edge of SCK signals the beginning of a transmission. At this time, the first bit of received data is accepted at the SDI pin and the first bit of transmitted data is presented at the SDO pin. Data is captured at the SDI pin on the rising edge of SCK. Subsequent falling edges shift the data and accept or present the next bit. The transmission is ended upon the eighth rising edge of SCK. The maximum frequency of SCK in slave mode is equal to E (bus clock) divided by four. That is, for a 4-MHz oscillator input, E becomes 2 MHz and the maximum SCK frequency is 0.5 MHz. There is no minimum SCK frequency.

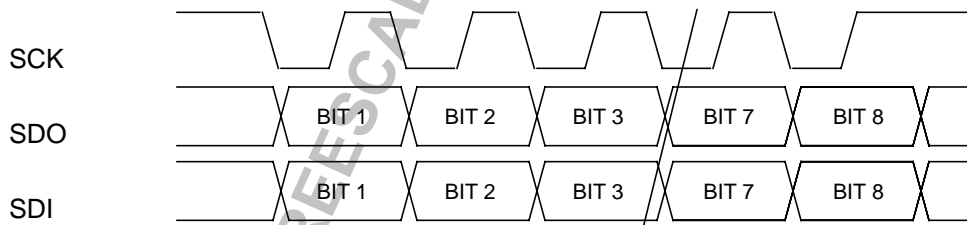
In master mode, the format is identical except that the SCK pin is an output and the shift clock now originates internally. The master mode transmission frequency is fixed at E/4.

### 7.1.2 Serial Data Out (SDO)

A mask programmable option will be included to allow data to be transmitted in either MSB first format or LSB first format. In either case, the state of the SDO pin always will reflect the value of the first bit received on the previous transmission if there was one. Prior to enabling the SIOP, PB5 can be initialized to determine the beginning state if necessary. While the SIOP is enabled, PB5 can not be used as a standard output since that pin is coupled to the last stage of the serial shift register. On the first falling edge of SCK, the first data bit to be shifted out is presented to the output pin.

### 7.1.3 Serial Data In (SDI)

The SDI pin becomes an input as soon as the SIOP is enabled. New data may be presented to the SDI pin on the falling edge of SCK. Valid data must be present at least 100 ns before the rising edge of the clock and remain valid for 100 ns after the edge.



**Figure 7-2. Serial I/O Port Timing**



**7.2 SIOP Registers**

The following paragraphs describe the SIOP registers.

**7.2.1 SIOP Control Register (SCR)**

This register is located at address \$000A and contains two bits.

\$0A	0	SPE	0	MSTR	0	0	0	0
RESET:	0	0	0	0	0	0	0	0

**Figure 7-3. SIOP Control Register**

**SPE — Serial Peripheral Enable**

When set, this bit enables the serial I/O port and initializes the port B DDR such that PB5 (SDO) is output, PB6 (SDI) is input and PB7 (SCK) is input (slave mode only). The port B DDR can be altered subsequently as the application requires and the port B data register (except for PB5) can be manipulated as usual. However, these actions could affect the transmitted or received data. When SPE is cleared, port B reverts to standard parallel I/O without affecting the port B data register or DDR. SPE is readable and writable any time but clearing SPE while a transmission is in progress will abort the transmission, reset the bit counter, and return port B to its normal I/O function. Reset clears this bit.

**MSTR — Master Mode**

When set, this bit configures the SIOP for master mode. This means that the transmission is initiated by a write to the data register and the SCK pin becomes an output providing a synchronous data clock at a fixed rate of E (bus clock) divided by four. While the device is in master mode, the SDO and SDI pins do not change function. These pins behave exactly as they would in slave mode. Reset clears this bit and configures the SIOP for slave operation. MSTR may be set at any time regardless of the state of SPE. Clearing MSTR will abort any transmission in progress.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**7.2.2 SIOP Status Register (SSR)**

This register is located at address \$000B and contains only two bits.

\$0B	SPIF	DCOL	0	0	0	0	0	0
RESET:	0	0	0	0	0	0	0	0

**Figure 7-4. SIOP Status Register**

**SPIF — Serial Peripheral Interface Flag**

This bit is set upon occurrence of the last rising clock edge and indicates that a data transfer has taken place. It has no effect on any further transmissions and can be ignored without problem. SPIF is cleared by reading the SSR with SPIF set followed by a read or write of the serial data register. If it is cleared before the last edge of the next byte, it will be set again. Reset clears this bit.

**DCOL — Data Collision**

This is a read-only status bit which indicates that an invalid access to the data register has been made. This can occur any time after the first falling edge of SCK and before SPIF is set. A read or write of the data register during this time will result in invalid data being transmitted or received.

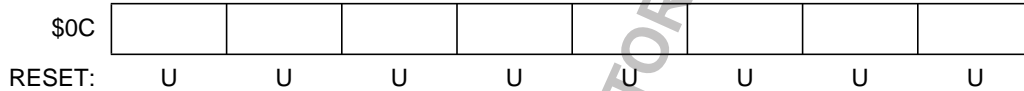
DCOL is cleared by reading the status register with SPIF set followed by a read or write of the data register. If the last part of the clearing sequence is done after another transmission has been started, DCOL will be set again. If the DCOL bit is set and the SPIF is not set, clearing the DCOL requires turning the SIOP off then turning it back on. Reset also clears this bit.

Freescale Semiconductor, Inc.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2008

### 7.2.3 SIOP Data Register (SDR)

This register is located at address \$000C and is both the transmit and receive data register. This system is not double buffered and any write to this register will destroy the previous contents. The SDR can be read at any time, but if a transmission is in progress the results may be ambiguous. Writes to the SDR while a transmission is in progress can cause invalid data to be transmitted and/or received. This register can be read and written only when the SIOP is enabled (SPE=1).



**Figure 7-5. SIOP Data Register**

Freescale Semiconductor, Inc.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

## SECTION 8 TIMER

The timer consists of a 16-bit, software-programmable counter driven by a fixed divide-by-four prescaler. This timer can be used for many purposes, including input waveform measurements while simultaneously generating an output waveform. Pulse widths can vary from several microseconds to many seconds. Refer to **Figure 8-1** for a timer block diagram.

Each specific functional segment (capability) is represented by two registers. These registers contain the high and low byte of that functional segment. Generally, accessing the low byte of a specific timer function allows full control of that function; however, an access of the high byte inhibits that specific timer function until the low byte also is accessed.

---

### NOTE

The I bit in the CCR should be set while manipulating both the high and low byte register of a specific timer function to ensure that an interrupt does not occur.

---

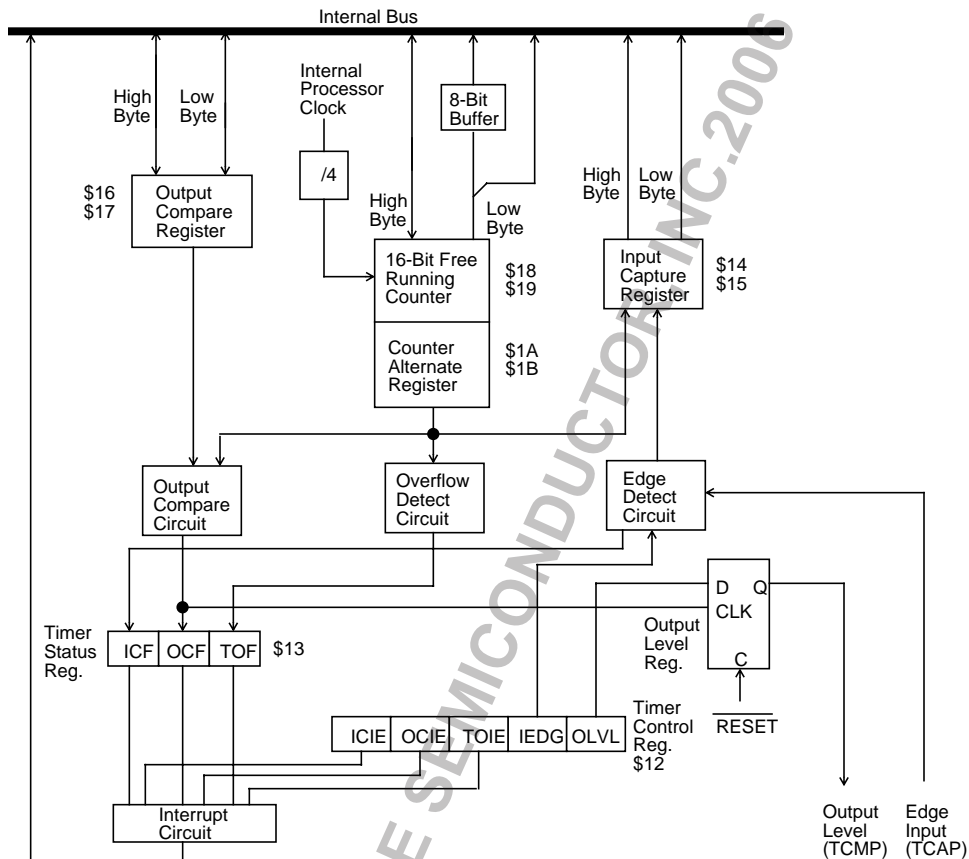


Figure 8-1. Timer Block Diagram

## 8.1 Counter

The key element in the programmable timer is a 16-bit, free-running counter or counter register, preceded by a prescaler that divides the internal processor clock by four. The prescaler gives the timer a resolution of 2.0 microseconds if the internal bus clock is 2.0 MHz. The counter is incremented during the low portion of the internal bus clock. Software can read the counter at any time without affecting its value.

The double-byte, free-running counter can be read from either of two locations, \$18-\$19 (counter register) or \$1A-\$1B (counter alternate register). A read from only the least significant byte (LSB) of the free-running counter (\$19, \$1B) receives the count value at the time of the read. If a read of the free-running counter or counter alternate register first addresses the most significant byte (MSB) (\$18, \$1A), the LSB (\$19, \$1B) is transferred to a buffer. This buffer value remains fixed after the first MSB read, even if the user reads the MSB several

times. This buffer is accessed when reading the free-running counter or counter alternate register LSB (\$19 or \$1B) and, thus, completes a read sequence of the total counter value. In reading either the free-running counter or counter alternate register, if the MSB is read, the LSB also must be read to complete the sequence.

The counter alternate register differs from the counter register in one respect: Aread of the counter register MSB can clear the timer overflow flag (TOF). Therefore, the counter alternate register can be read at any time without the possibility of missing timer overflow interrupts due to clearing of the TOF.

The free-running counter is configured to \$FFFC during reset and is always a read-only register. During a power-on reset, the counter is also preset to \$FFFC and begins running after the oscillator start-up delay. Because the free-running counter is 16 bits preceded by a fixed divided-by-four prescaler, the value in the free-running counter repeats every 262,144 internal bus clock cycles. When the counter rolls over from \$FFFF to \$0000, the TOF bit is set. An interrupt can also be enabled when counter rollover occurs by setting its interrupt enable bit (TOIE).

## 8.2 Output Compare Register

The 16-bit output compare register is made up of two 8-bit registers at locations \$16 (MSB) and \$17 (LSB). The output compare register is used for several purposes, such as indicating when a period of time has elapsed. All bits are readable and writable and are not altered by the timer hardware or reset. If the compare function is not needed, the two bytes of the output compare register can be used as storage locations.

The output compare register contents are compared with the contents of the free-running counter continually, and if a match is found, the corresponding output compare flag (OCF) bit is set and the corresponding output level (OLVL) bit is clocked to an output level register. The output compare register values and the output level bit should be changed after each successful comparison to establish a new elapsed timeout. An interrupt can also accompany a successful output compare provided the corresponding interrupt enable bit (OCIE) is set.

After a processor write cycle to the output compare register containing the MSB (\$16), the output compare function is inhibited until the LSB (\$17) is also written. The user must write both bytes (locations) if the MSB is written first. A write made only to the LSB (\$17) will not inhibit the compare function. The free-running counter is updated every four internal bus clock cycles. The minimum time required to update the output compare register is a function of the program rather than the internal hardware.

The processor can write to either byte of the output compare register without affecting the other byte. The output level (OLVL) bit is clocked to the output level register regardless of whether the output compare flag (OCF) is set or clear.

### 8.3 Input Capture Register

Two 8-bit registers, which make up the 16-bit input capture register, are read-only and are used to latch the value of the free-running counter after the corresponding input capture edge detector senses a defined transition. The level transition which triggers the counter transfer is defined by the corresponding input edge bit (IEDG). Reset does not affect the contents of the input capture register.

The result obtained by an input capture will be one more than the value of the free-running counter on the rising edge of the internal bus clock preceding the external transition. This delay is required for internal synchronization. Resolution is one count of the free-running counter, which is four internal bus clock cycles.

The free-running counter contents are transferred to the input capture register on each proper signal transition regardless of whether the input capture flag (ICF) is set or clear. The input capture register always contains the free-running counter value that corresponds to the most recent input capture.

After a read of the input capture register (\$14) MSB, the counter transfer is inhibited until the LSB (\$15) is also read. This characteristic causes the time used in the input capture software routine and its interaction with the main program to determine the minimum pulse period.

A read of the input capture register LSB (\$15) does not inhibit the free-running counter transfer since they occur on opposite edges of the internal bus clock.



**8.4 Timer Control Register (TCR) \$12**

The TCR is a read/write register containing five control bits. Three bits control interrupts associated with the timer status register flags ICF, OCF, and TOF.

\$12	ICIE	OCIE	TOIE	0	0	0	IEDG	OLVL
RESET:	0	0	0	0	0	0	0	0

**Figure 8-2. Timer Control Register**

ICIE — Input Capture Interrupt Enable

- 1 = Interrupt enabled
- 0 = Interrupt disabled

OCIE — Output Compare Interrupt Enable

- 1 = Interrupt enabled
- 0 = Interrupt disabled

TOIE — Timer Overflow Interrupt Enable

- 1 = Interrupt enabled
- 0 = Interrupt disabled

IEDG — Input Edge

Value of input edge determines which level transition on TCAP pin will trigger free-running counter transfer to the input capture register

- 1 = Positive edge
- 0 = Negative edge

Reset does not affect the IEDG bit (U=unaffected).

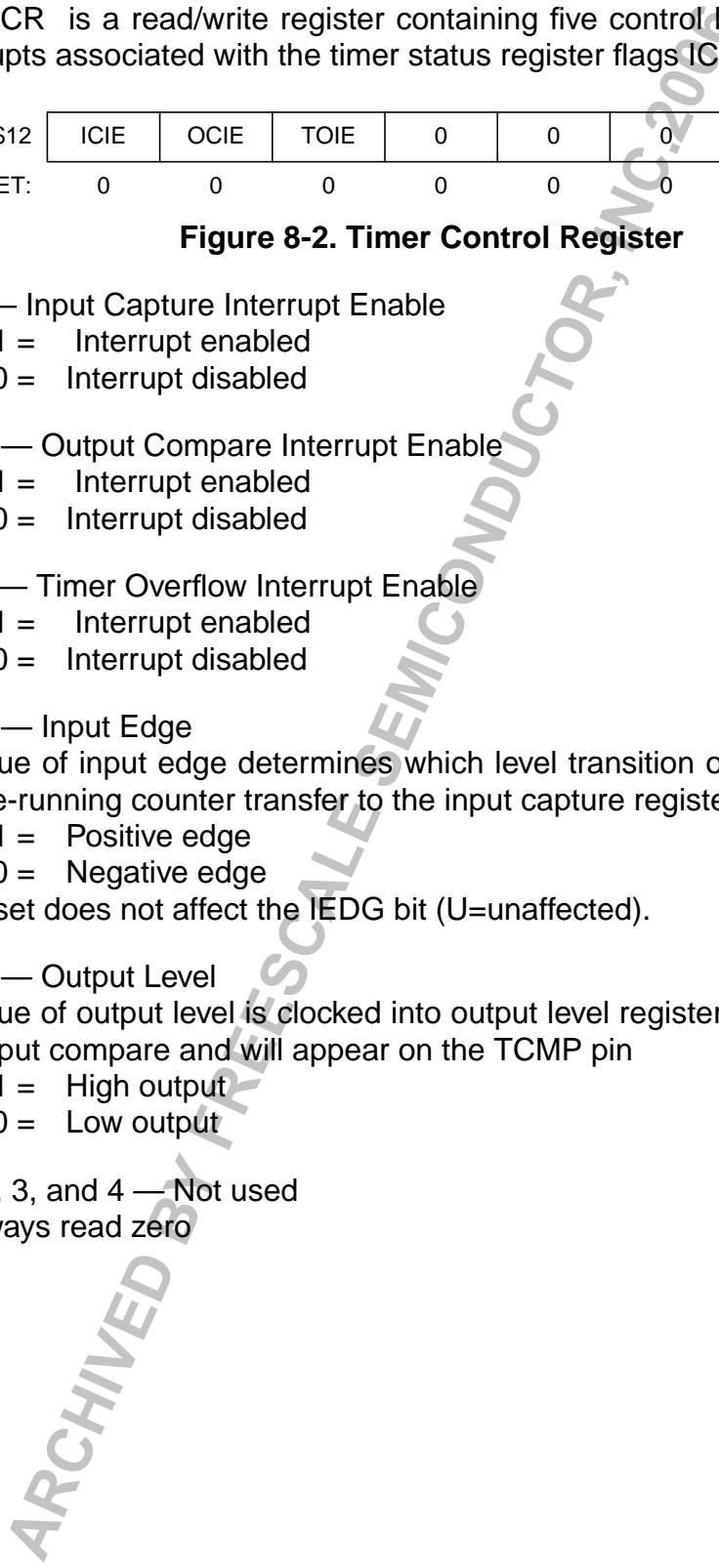
OLVL — Output Level

Value of output level is clocked into output level register by the next successful output compare and will appear on the TCMP pin

- 1 = High output
- 0 = Low output

Bits 2, 3, and 4 — Not used

Always read zero



**8.5 Timer Status Register (TSR) \$13**

The TSR is a read-only register containing three status flag bits.

\$13	ICF	OCF	TOF	0	0	0	0	0
RESET:	U	U	U	0	0	0	0	0

**Figure 8-3. Timer Status Register**

ICF — Input Capture Flag

- 1 = Flag set when selected polarity edge is sensed by input capture edge detector
- 0 = Flag cleared when TSR and input capture low register (\$15) are accessed

OCF — Output Compare Flag

- 1 = Flag set when output compare register contents match the free-running counter contents
- 0 = Flag cleared when TSR and output compare low register (\$17) are accessed

TOF — Timer Overflow Flag

- 1 = Flag set when free-running counter transition from \$FFFF to \$0000 occurs
- 0 = Flag cleared when TSR and counter low register (\$19) are accessed

Bits 0-4 — Not used  
Always read zero

Accessing the timer status register satisfies the first condition required to clear status bits. The remaining step is to access the register corresponding to the status bit.

A problem can occur when using the timer overflow function and reading the free-running counter at random times to measure an elapsed time. Without incorporating the proper precautions into software, the timer overflow flag could unintentionally be cleared if:

1. The timer status register is read or written when TOF is set, and
2. The LSB of the free-running counter is read but not for the purpose of servicing the flag.

The counter alternate register at address \$1A and \$1B contains the same value as the free-running counter (at address \$18 and \$19); therefore, this alternate register can be read at any time without affecting the timer overflow flag in the timer status register.

**8.6 Timer During Wait or Halt Mode**

The CPU clock halts during the wait or halt mode, but the timer remains active. If interrupts are enabled, a timer interrupt will cause the processor to exit the wait mode.

**8.7 Timer During Stop Mode**

In the stop mode, the timer stops counting and holds the last count value if stop is exited by an interrupt. If  $\overline{\text{RESET}}$  is used, the counter is forced to \$FFFC. During stop, if at least one valid input capture edge occurs at the TCAP pin, the input capture detect circuit is armed. This does not set any timer flags wake up the MCU, but when the MCU does wake up, there is an active input capture flag and data from the first valid edge that occurred during the stop mode. If  $\overline{\text{RESET}}$  is used to exit stop mode, then no input capture flag or data remains, even if a valid input capture edge occurred.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

## SECTION 9 COMPUTER OPERATING PROPERLY (COP)

This device includes a watchdog COP feature as a mask option. The COP is implemented with an 18-bit ripple counter. This provides a timeout period of 64 milliseconds at a bus rate of 2 MHz. If the COP should timeout, a system reset will occur and the device will be re-initialized in the same fashion as a power-on reset (POR) or external reset.

### 9.1 Resetting The COP

Preventing a COP reset is done by writing a zero to the COPR bit. This action will reset the counter and begin the timeout period again. The COPR bit is bit 0 of address \$1FF0. A read of address \$1FF0 will access the user-defined ROM data at that location.

### 9.2 COP During Wait or Halt Mode

The COP will continue to operate normally during wait or halt mode. The software should pull the device out of wait or halt mode periodically and reset the COP by writing a logic zero to the COPR bit to prevent a COP reset.

### 9.3 COP During Stop Mode

Stop mode disables the oscillator circuit and thereby turns the clock off for the entire device. The COP counter will be reset when stop mode is entered. If a reset is used to exit stop mode, the COP counter will be reset after the 4064 cycles of delay after stop mode. If an IRQ is used to exit stop mode, the COP counter will not be reset after the 4064-cycle delay and will have that many cycles already counted when control is returned to the program.

---

#### NOTE

The halt mode is not intended for normal use. This feature is provided to keep the COP watchdog timer active in the event a STOP instruction is inadvertently executed.

---

**Freescale Semiconductor, Inc.**

GENERAL RELEASE SPECIFICATION

**Freescale Semiconductor, Inc.**

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

## SECTION 10 ANALOG-TO-DIGITAL (A/D) CONVERTER

This section describes the four-channel, 8-bit, multiplexed input, successive-approximation A/D converter.

### 10.1 Conversion Process

The A/D conversion process is ratiometric, using two reference voltages,  $V_{RH}$  and  $V_{SS}$ . Conversion accuracy is guaranteed only if  $V_{RH}$  is equal to  $V_{DD}$ .

A multiplexer selects one of four analog input channels (AN3, AN2, AN1, or AN0) for sampling. A comparator successively compares the output of an internal digital-to-analog (D/A) converter to the sampled analog input. Control logic changes the D/A converter input one bit at a time, starting with the most significant bit (MSB), until the D/A converter output matches the sampled analog input. The conversion is monotonic and has no missing codes.

An analog input voltage equal to  $V_{RH}$  converts to digital \$FF; an input voltage greater than  $V_{RH}$  converts to \$FF with no overflow. An analog input voltage equal to  $V_{SS}$  converts to digital \$00. For ratiometric conversions, the source of each analog input should use  $V_{RH}$  as the supply voltage and be referenced to  $V_{SS}$ .

Pins PC6–PC3 are the four inputs to the multiplexer. Each channel of conversion takes 32 internal clock cycles, and the clock frequency must be equal to or greater than 1 MHz. If the internal clock frequency is less than 1 MHz, the A/D internal RC oscillator (nominally 1.5 MHz) must be used for the A/D conversion clock. Make this selection by setting the ADRC bit in the A/D status and control register to logical one.

**10.2 A/D Status and Control Register (ADSCR)**

The A/D status and control register contains a status flag and four writable control bits.

\$001E	CCF	ADRC	ADON	0	0	0	CH1	CH0
RESET:	0	0	0	0	0	0	0	0

**Figure 10-1. A/D Status and Control Register (ADSCR)**

**CCF — Conversion Complete Flag**

This read-only bit is automatically set when an analog-to-digital conversion is complete, and a new result can be read from the A/D data register. CCF is automatically cleared when a new conversion begins or when either the A/D status and control register or the A/D data register is accessed. Writing to or reading the A/D status and control register or the A/D data register starts a new conversion sequence. Data from the previous conversion is overwritten regardless of the state of the CCF bit. While CCF is a logical zero, the requested A/D result is not yet available in the A/D data register.

**ADRC — A/D RC Oscillator Control**

When the RC oscillator is turned on, it requires a time ( $t_{ADRC}$ ) to stabilize, and results can be inaccurate during this time. If the internal clock rate is above 1 MHz, the ADRC bit should be cleared.

- 1 = Internal RC oscillator drives A/D converter
- 0 = Internal clock drives A/D converter

When the internal RC oscillator is being used as the A/D converter clock, two limitations apply:

1. Because of the frequency tolerance of the RC oscillator and its asynchronism with the internal clock, the conversion complete flag (CCF) must be used to determine when a conversion sequence has been completed.
2. The conversion process runs at the nominal 1.5 MHz rate, but the conversion results must be transferred to the A/D data register synchronously with the internal clock; therefore, the conversion process is limited to a maximum of one channel every internal clock cycle.

**ADON — A/D On**

When the A/D is turned on, it requires a time ( $t_{ADON}$ ) for the current sources to stabilize. During this time, results can be inaccurate.

- 1 = A/D converter enabled
- 0 = A/D converter disabled

**Bits 4–2 — Not Used**

These bits are not used and read logical zero out of reset. Logical zeros must be written to these bits when writing the A/D status and control register.



CH1–CH0 — Channel Select

These bits select one of the four A/D inputs (AN3, AN2, AN1, or AN0) for conversion. Refer to Table 10-1).

**Table 10-1. A/D Input Selection**

CH1:CH0	Input Selected
00	AN0, Port C Bit 6
01	AN1, Port C Bit 5
10	AN2, Port C Bit 4
11	AN3, Port C Bit 3

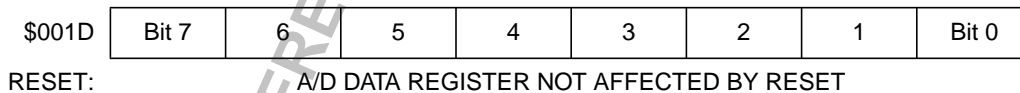
To prevent excess power dissipation, do not use a port C pin as an analog input and a digital input at the same time.

Using one of the port C pins as the A/D converter input does not affect the ability to use the remaining port C pins as digital inputs.

Performing a digital read of a port C pin that is selected as an analog input returns a logical zero.

**10.3 A/D Data Register (ADDR)**

The A/D data register is a read-only register that contains the result of the most recent A/D conversion. This register is updated each time the conversion complete flag (CCF) is set in the A/D status and control register.



**Figure 10-2. A/D Data Register (ADDR)**

**10.4 A/D Converter During Wait Mode**

The A/D converter continues to operate normally while the MCU is in wait mode. If the A/D converter is not being used, clear the ADON and ADRC bits in the A/D status and control register to decrease power consumption during wait mode.

**10.5 A/D Converter During Stop or Halt Mode**

Stop or halt mode disables the comparator and charge pump and aborts any conversion in progress or pending. When the MCU leaves stop mode, the built-in delay for oscillator startup allows enough time for the A/D circuits to stabilize. Therefore, no software delays are needed after exiting from stop mode. When the MCU leaves halt mode, a software delay is needed since the MCU may exit from halt mode after only one internal clock cycle.

**SECTION 11  
SELF-CHECK MODE**

The self-check program resides at mask ROM locations \$1F00 to \$1FEF. This program is designed to check the part's functionality with a minimum of support hardware. The COP subsystem is disabled in the self-check mode so that routines that feed the COP do not exist in the self-check program.

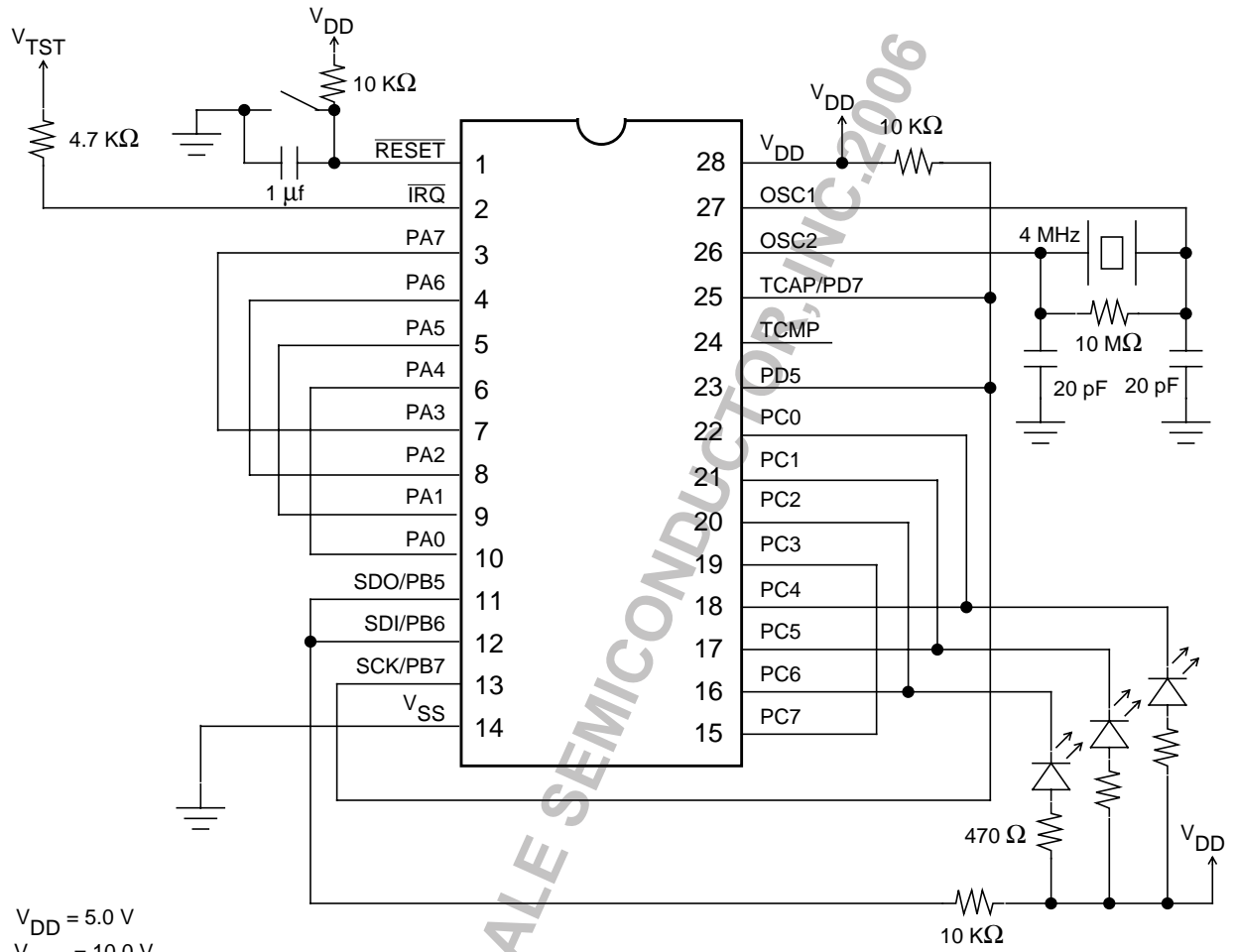
The self-check mode is entered on the rising edge of  $\overline{\text{RESET}}$  if the  $\overline{\text{IRQ}}$  pin is driven to double the supply voltage and the TCAP/PD7 pin is at logic one.  $\overline{\text{RESET}}$  must be held low for 4064 cycles after POR or for a time  $t_{\text{RL}}$  for any other reset. After reset, the I/O, RAM, ROM, timer, and SIOPI are tested. Self-check results (using LED's as monitors) are shown in Table 11-1. It is not recommended that the user code use any of the self-check code. The self-check code is subject to change at any time to improve testability or manufacturability.

**Table 11-1. Self-Check Results**

PC2	PC1	PC0	REMARKS
0	0	1	Bad I/O
0	1	0	Bad RAM
0	1	1	Bad Timer
1	0	0	Bad ROM
1	0	1	Bad Serial
Flashing			Good Device
All Others			Bad Device

0 indicates LED is on; 1 indicates LED is off.

ARCHIVED BY FREESCALE SEMICONDUCTOR INC. 2006



**Figure 11-1. Self-Check Circuit**

Freescale Semiconductor, Inc.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

## SECTION 12 INSTRUCTION SET

This section describes the M68HC05P9A addressing modes and instruction types.

### 12.1 Addressing Modes

The CPU uses eight addressing modes for flexibility in accessing data. The addressing modes define the manner in which the CPU finds the data required to execute an instruction. The eight addressing modes are the following:

- Inherent
- Immediate
- Direct
- Extended
- Indexed, no offset
- Indexed, 8-bit offset
- Indexed, 16-bit offset
- Relative

#### 12.1.1 Inherent

Inherent instructions are those that have no operand, such as return from interrupt (RTI) and stop (STOP). Some of the inherent instructions act on data in the CPU registers, such as set carry flag (SEC) and increment accumulator (INCA). Inherent instructions require no memory address and are one byte long.

### 12.1.2 Immediate

Immediate instructions are those that contain a value to be used in an operation with the value in the accumulator or index register. Immediate instructions require no memory address and are two bytes long. The opcode is the first byte, and the immediate data value is the second byte.

### 12.1.3 Direct

Direct instructions can access any of the first 256 memory addresses with two bytes. The first byte is the opcode, and the second is the low byte of the operand address. In direct addressing, the CPU automatically uses \$00 as the high byte of the operand address. BRSET and BRCLR are three-byte instructions that use direct addressing to access the operand and relative addressing to specify a branch destination.

### 12.1.4 Extended

Extended instructions use only three bytes to access any address in memory. The first byte is the opcode; the second and third bytes are the high and low bytes of the operand address.

When using the Motorola assembler, the programmer does not need to specify whether an instruction is direct or extended. The assembler automatically selects the shortest form of the instruction.

### 12.1.5 Indexed, No Offset

Indexed instructions with no offset are one-byte instructions that can access data with variable addresses within the first 256 memory locations. The index register contains the low byte of the conditional address of the operand. The CPU automatically uses \$00 as the high byte, so these instructions can address locations \$0000–\$00FF.

Indexed, no offset instructions are often used to move a pointer through a table or to hold the address of a frequently used RAM or I/O location.

### 12.1.6 Indexed, 8-Bit Offset

Indexed, 8-bit offset instructions are two-byte instructions that can access data with variable addresses within the first 511 memory locations. The CPU adds the unsigned byte in the index register to the unsigned byte following the opcode. The sum is the conditional address of the operand. These instructions can access locations \$0000–\$01FE.

Indexed 8-bit offset instructions are useful for selecting the kth element in an n-element table. The table can begin anywhere within the first 256 memory locations and could extend as far as location 510 (\$01FE). The k value is typically in the index register, and the address of the beginning of the table is in the byte following the opcode.

### 12.1.7 Indexed, 16-Bit Offset

Indexed, 16-bit offset instructions are three-byte instructions that can access data with variable addresses at any location in memory. The CPU adds the unsigned byte in the index register to the two unsigned bytes following the opcode. The sum is the conditional address of the operand. The first byte after the opcode is the high byte of the 16-bit offset; the second byte is the low byte of the offset. These instructions can address any location in memory.

Indexed, 16-bit offset instructions are useful for selecting the kth element in an n-element table anywhere in memory.

As with direct and extended addressing the Motorola assembler determines the shortest form of indexed addressing.

### 12.1.8 Relative

Relative addressing is only for branch instructions. If the branch condition is true, the CPU finds the conditional branch destination by adding the signed byte following the opcode to the contents of the program counter. If the branch condition is not true, the CPU goes to the next instruction. The offset is a signed, two's complement byte that gives a branching range of  $-128$  to  $+127$  bytes from the address of the next location after the branch instruction.

When using the Motorola assembler, the programmer does not need to calculate the offset, because the assembler determines the proper offset and verifies that it is within the span of the branch.

## 12.2 Instruction Types

The MCU instructions fall into the following five categories:

- Register/Memory Instructions
- Read-Modify-Write Instructions
- Jump/Branch Instructions
- Bit Manipulation Instructions
- Control Instructions

### 12.2.1 Register/Memory Instructions

Most of these instructions use two operands. One operand is in either the accumulator or the index register. The CPU finds the other operand in memory. Table 12-1 lists the register/memory instructions.

**Table 12-1. Register/Memory Instructions**

Instruction	Mnemonic
Add Memory Byte and Carry Bit to Accumulator	ADC
Add Memory Byte to Accumulator	ADD
AND Memory Byte with Accumulator	AND
Bit Test Accumulator	BIT
Compare Accumulator	CMP
Compare Index Register with Memory Byte	CPX
EXCLUSIVE OR Accumulator with Memory Byte	EOR
Load Accumulator with Memory Byte	LDA
Load Index Register with Memory Byte	LDX
Multiply	MUL
OR Accumulator with Memory Byte	ORA
Subtract Memory Byte and Carry Bit from Accumulator	SBC
Store Accumulator in Memory	STA
Store Index Register in Memory	STX
Subtract Memory Byte from Accumulator	SUB



**12.2.2 Read-Modify-Write Instructions**

These instructions read a memory location or a register, modify its contents, and write the modified value back to the memory location or to the register. The test for negative or zero instruction (TST) is an exception to the read-modify-write sequence because it does not write a replacement value. Table 12-2 lists the read-modify-write instructions.

**Table 12-2. Read-Modify-Write Instructions**

Instruction	Mnemonic
Arithmetic Shift Left	ASL
Arithmetic Shift Right	ASR
Clear Bit in Memory	BCLR
Set Bit in Memory	BSET
Clear	CLR
Complement (One's Complement)	COM
Decrement	DEC
Increment	INC
Logical Shift Left	LSL
Logical Shift Right	LSR
Negate (Two's Complement)	NEG
Rotate Left through Carry Bit	ROL
Rotate Right through Carry Bit	ROR
Test for Negative or Zero	TST

**12.2.3 Jump/Branch Instructions**

Jump instructions allow the CPU to interrupt the normal sequence of the program counter. The unconditional jump instruction (JMP) and the jump to subroutine instruction (JSR) have no register operand. Branch instructions allow the CPU to interrupt the normal sequence of the program counter when a test condition is met. If the test condition is not met, the branch is not performed. All branch instructions use relative addressing.

Bit test and branch instructions cause a branch based on the state of any readable bit in the first 256 memory locations. These three-byte instructions use a combination of direct addressing and relative addressing. The direct address of the byte to be tested is in the byte following the opcode. The third byte is the signed offset byte. The CPU finds the conditional branch destination by adding the

third byte to the program counter if the specified bit tests true. The bit to be tested and its condition (set or clear) is part of the opcode. The span of branching is from -128 to +127 from the address of the next location after the branch instruction. The CPU also transfers the tested bit to the carry/borrow bit of the condition code register. Table 12-3 lists the jump and branch instructions.

**Table 12-3. Jump and Branch Instructions**

Instruction	Mnemonic
Branch if Carry Bit Clear	BCC
Branch if Carry Bit Set	BCS
Branch if Equal	BEQ
Branch if Half-Carry Bit Clear	BHCC
Branch if Half-Carry Bit Set	BHCS
Branch if Higher	BHI
Branch if Higher or Same	BHS
Branch if $\overline{\text{IRQ}}$ Pin High	BIH
Branch if $\overline{\text{IRQ}}$ Pin Low	BIL
Branch if Lower	BLO
Branch if Lower or Same	BLS
Branch if Interrupt Mask Clear	BMC
Branch if Minus	BMI
Branch if Interrupt Mask Set	BMS
Branch if Not Equal	BNE
Branch if Plus	BPL
Branch Always	BRA
Branch if Bit Clear	BRCLR
Branch Never	BRN
Branch if Bit Set	BRSET
Branch to Subroutine	BSR
Unconditional Jump	JMP
Jump to Subroutine	JSR

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

**12.2.4 Bit Manipulation Instructions**

The CPU can set or clear any writable bit in the first 256 bytes of memory. Port registers, port data direction registers, timer registers, and on-chip RAM locations are in the first 256 bytes of memory. The CPU can also test and branch based on the state of any bit in any of the first 256 memory locations. Bit manipulation instructions use direct addressing. Table 12-4 lists these instructions.

**Table 12-4. Bit Manipulation Instructions**

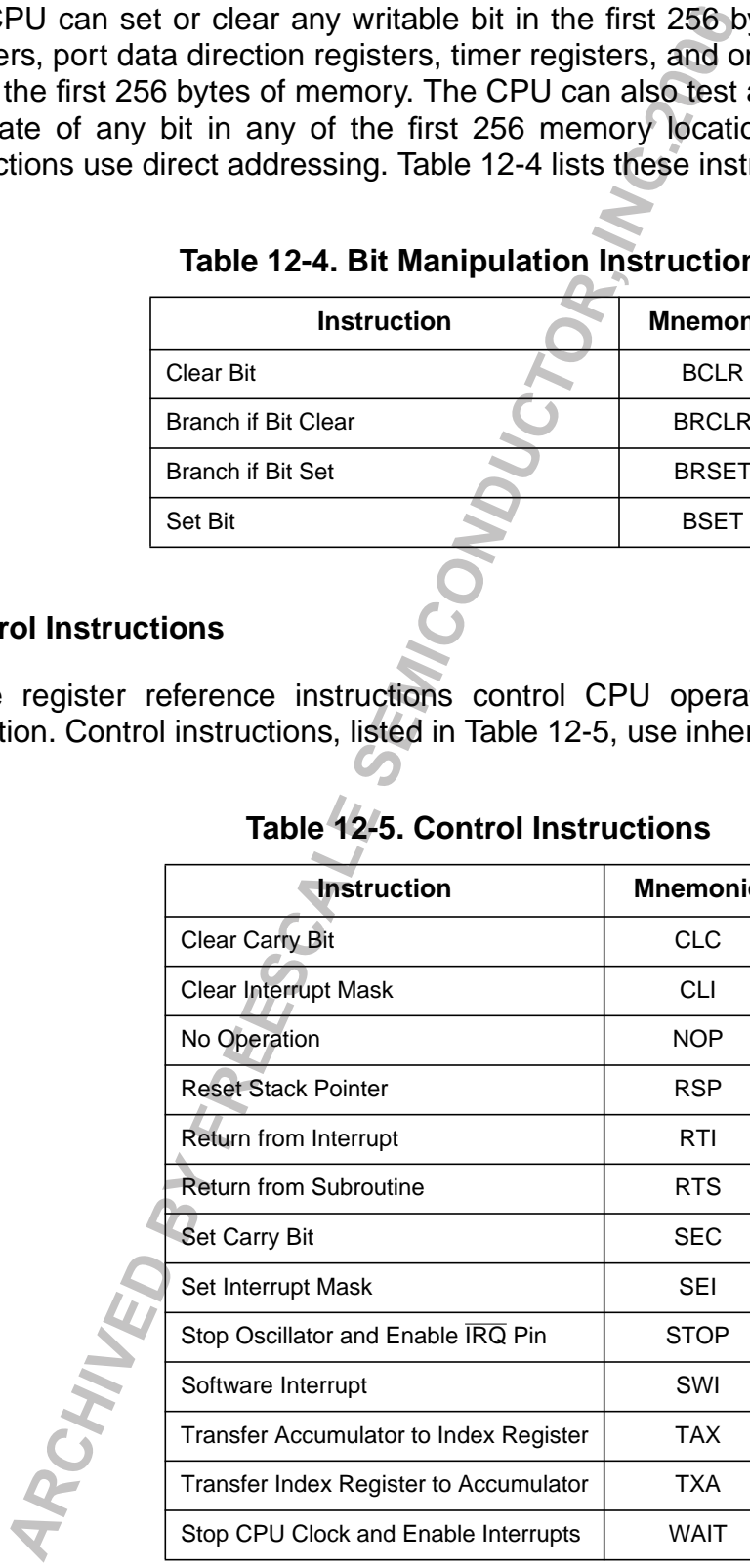
Instruction	Mnemonic
Clear Bit	BCLR
Branch if Bit Clear	BRCLR
Branch if Bit Set	BRSET
Set Bit	BSET

**12.2.5 Control Instructions**

These register reference instructions control CPU operation during program execution. Control instructions, listed in Table 12-5, use inherent addressing.

**Table 12-5. Control Instructions**

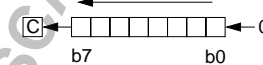
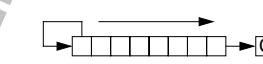
Instruction	Mnemonic
Clear Carry Bit	CLC
Clear Interrupt Mask	CLI
No Operation	NOP
Reset Stack Pointer	RSP
Return from Interrupt	RTI
Return from Subroutine	RTS
Set Carry Bit	SEC
Set Interrupt Mask	SEI
Stop Oscillator and Enable $\bar{I}RQ$ Pin	STOP
Software Interrupt	SWI
Transfer Accumulator to Index Register	TAX
Transfer Index Register to Accumulator	TXA
Stop CPU Clock and Enable Interrupts	WAIT



12.3 Instruction Set Summary

Table 12-6 is an alphabetical list of all M68HC05 instructions and shows the effect of each instruction on the condition code register.

Table 12-6. Instruction Set Summary

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles
			H	I	N	Z	C				
ADC #opr ADC opr ADC opr ADC opr,X ADC opr,X ADC ,X	Add with Carry	$A \leftarrow (A) + (M) + (C)$	↑	—	↑	↑	↑	IMM DIR EXT IX2 IX1 IX	A9 B9 C9 D9 E9 F9	ii dd hh ll ee ff ff	2 3 4 5 4 3
ADD #opr ADD opr ADD opr ADD opr,X ADD opr,X ADD ,X	Add without Carry	$A \leftarrow (A) + (M)$	↑	—	↑	↑	↑	IMM DIR EXT IX2 IX1 IX	AB BB CB DB EB FB	ii dd hh ll ee ff ff	2 3 4 5 4 3
AND #opr AND opr AND opr AND opr,X AND opr,X AND ,X	Logical AND	$A \leftarrow (A) \wedge (M)$	—	—	↑	↑	—	IMM DIR EXT IX2 IX1 IX	A4 B4 C4 D4 E4 F4	ii dd hh ll ee ff ff	2 3 4 5 4 3
ASL opr ASLA ASLX ASL opr,X ASL ,X	Arithmetic Shift Left (Same as LSL)		—	—	↑	↑	↑	DIR INH INH IX1 IX	38 48 58 68 78	dd	5 3 3 6 5
ASR opr ASRA ASRX ASR opr,X ASR ,X	Arithmetic Shift Right		—	—	↑	↑	↑	DIR INH INH IX1 IX	37 47 57 67 77	dd	5 3 3 6 5
BCC rel	Branch if Carry Bit Clear	$PC \leftarrow (PC) + 2 + rel ? C = 0$	—	—	—	—	—	REL	24	rr	3
BCLR n opr	Clear Bit n	$M_n \leftarrow 0$	—	—	—	—	—	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	11 13 15 17 19 1B 1D 1F	dd dd dd dd dd dd dd dd	5 5 5 5 5 5 5 5
BCS rel	Branch if Carry Bit Set (Same as BLO)	$PC \leftarrow (PC) + 2 + rel ? C = 1$	—	—	—	—	—	REL	25	rr	3
BEQ rel	Branch if Equal	$PC \leftarrow (PC) + 2 + rel ? Z = 1$	—	—	—	—	—	REL	27	rr	3

Freescale Semiconductor, Inc.

Table 12-6. Instruction Set Summary (Continued)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles
			H	I	N	Z	C				
BHCC <i>rel</i>	Branch if Half-Carry Bit Clear	$PC \leftarrow (PC) + 2 + rel ? H = 0$	—	—	—	—	—	REL	28	rr	3
BHCS <i>rel</i>	Branch if Half-Carry Bit Set	$PC \leftarrow (PC) + 2 + rel ? H = 1$	—	—	—	—	—	REL	29	rr	3
BHI <i>rel</i>	Branch if Higher	$PC \leftarrow (PC) + 2 + rel ? C \vee Z = 0$	—	—	—	—	—	REL	22	rr	3
BHS <i>rel</i>	Branch if Higher or Same	$PC \leftarrow (PC) + 2 + rel ? C = 0$	—	—	—	—	—	REL	24	rr	3
BIH <i>rel</i>	Branch if $\overline{IRQ}$ Pin High	$PC \leftarrow (PC) + 2 + rel ? \overline{IRQ} = 1$	—	—	—	—	—	REL	2F	rr	3
BIL <i>rel</i>	Branch if $\overline{IRQ}$ Pin Low	$PC \leftarrow (PC) + 2 + rel ? \overline{IRQ} = 0$	—	—	—	—	—	REL	2E	rr	3
BIT # <i>opr</i> BIT <i>opr</i> BIT <i>opr</i> ,X BIT <i>opr</i> ,X BIT <i>opr</i> ,X BIT ,X	Bit Test Accumulator with Memory Byte	(A) ^ (M)	—	—	↕	↕	—	IMM DIR EXT IX2 IX1 IX	A5 B5 C5 D5 E5 F5	ii dd hh ll ee ff ff p	2 3 4 5 4 3
BLO <i>rel</i>	Branch if Lower (Same as BCS)	$PC \leftarrow (PC) + 2 + rel ? C = 1$	—	—	—	—	—	REL	25	rr	3
BLS <i>rel</i>	Branch if Lower or Same	$PC \leftarrow (PC) + 2 + rel ? C \vee Z = 1$	—	—	—	—	—	REL	23	rr	3
BMC <i>rel</i>	Branch if Interrupt Mask Clear	$PC \leftarrow (PC) + 2 + rel ? I = 0$	—	—	—	—	—	REL	2C	rr	3
BMI <i>rel</i>	Branch if Minus	$PC \leftarrow (PC) + 2 + rel ? N = 1$	—	—	—	—	—	REL	2B	rr	3
BMS <i>rel</i>	Branch if Interrupt Mask Set	$PC \leftarrow (PC) + 2 + rel ? I = 1$	—	—	—	—	—	REL	2D	rr	3
BNE <i>rel</i>	Branch if Not Equal	$PC \leftarrow (PC) + 2 + rel ? Z = 0$	—	—	—	—	—	REL	26	rr	3
BPL <i>rel</i>	Branch if Plus	$PC \leftarrow (PC) + 2 + rel ? N = 0$	—	—	—	—	—	REL	2A	rr	3
BRA <i>rel</i>	Branch Always	$PC \leftarrow (PC) + 2 + rel ? 1 = 1$	—	—	—	—	—	REL	20	rr	3
BRCLR <i>n opr rel</i>	Branch if bit n clear	$PC \leftarrow (PC) + 2 + rel ? Mn = 0$	—	—	—	—	↕	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	01 03 05 07 09 0B 0D 0F	dd rr dd rr dd rr dd rr dd rr dd rr dd rr dd rr	5 5 5 5 5 5 5 5
BRSET <i>n opr rel</i>	Branch if Bit n Set	$PC \leftarrow (PC) + 2 + rel ? Mn = 1$	—	—	—	—	↕	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	00 02 04 06 08 0A 0C 0E	dd rr dd rr dd rr dd rr dd rr dd rr dd rr dd rr	5 5 5 5 5 5 5 5
BRN <i>rel</i>	Branch Never	$PC \leftarrow (PC) + 2 + rel ? 1 = 0$	—	—	—	—	—	REL	21	rr	3

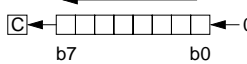
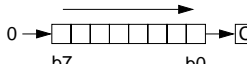
INSTRUCTION SET

Table 12-6. Instruction Set Summary (Continued)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles	
			H	I	N	Z	C					
BSET <i>n opr</i>	Set Bit <i>n</i>	$M_n \leftarrow 1$						DIR (b0)	10	dd	5	
								DIR (b1)	12	dd	5	
								DIR (b2)	14	dd	5	
								DIR (b3)	16	dd	5	
								DIR (b4)	18	dd	5	
								DIR (b5)	1A	dd	5	
								DIR (b6)	1C	dd	5	
						DIR (b7)	1E	dd	5			
BSR <i>rel</i>	Branch to Subroutine	PC $\leftarrow$ (PC) + 2; push (PCL) SP $\leftarrow$ (SP) - 1; push (PCH) SP $\leftarrow$ (SP) - 1 PC $\leftarrow$ (PC) + <i>rel</i>						REL	AD	rr	6	
CLC	Clear Carry Bit	$C \leftarrow 0$					0	INH	98		2	
CLI	Clear Interrupt Mask	$I \leftarrow 0$		0				INH	9A		2	
CLR <i>opr</i> CLRA CLR X CLR <i>opr,X</i> CLR ,X	Clear Byte	$M \leftarrow \$00$						DIR	3F	dd	5	
		$A \leftarrow \$00$						INH	4F		3	
		$X \leftarrow \$00$			0	1			INH	5F		3
		$M \leftarrow \$00$							IX1	6F	ff	6
		$M \leftarrow \$00$							IX	7F		5
CMP # <i>opr</i> CMP <i>opr</i> CMP <i>opr</i> CMP <i>opr,X</i> CMP <i>opr,X</i> CMP ,X	Compare Accumulator with Memory Byte	$(A) - (M)$			$\updownarrow$	$\updownarrow$	$\updownarrow$	IMM	A1	ii	2	
								DIR	B1	dd	3	
									EXT	C1	hh ll	4
									IX2	D1	ee ff	5
									IX1	E1	ff	4
							IX	F1		3		
COM <i>opr</i> COMA COM X COM <i>opr,X</i> COM ,X	Complement Byte (One's Complement)	$M \leftarrow (\overline{M}) = \$FF - (M)$						DIR	33	dd	5	
		$A \leftarrow (\overline{A}) = \$FF - (M)$						INH	43		3	
		$X \leftarrow (\overline{X}) = \$FF - (M)$			$\updownarrow$	$\updownarrow$	1		INH	53		3
		$M \leftarrow (\overline{M}) = \$FF - (M)$							IX1	63	ff	6
		$M \leftarrow (\overline{M}) = \$FF - (M)$							IX	73		5
CPX # <i>opr</i> CPX <i>opr</i> CPX <i>opr</i> CPX <i>opr,X</i> CPX <i>opr,X</i> CPX ,X	Compare Index Register with Memory Byte	$(X) - (M)$			$\updownarrow$	$\updownarrow$	1	IMM	A3	ii	2	
								DIR	B3	dd	3	
									EXT	C3	hh ll	4
									IX2	D3	ee ff	5
									IX1	E3	ff	4
							IX	F3		3		
DEC <i>opr</i> DECA DEC X DEC <i>opr,X</i> DEC ,X	Decrement Byte	$M \leftarrow (M) - 1$						DIR	3A	dd	5	
		$A \leftarrow (A) - 1$						INH	4A		3	
		$X \leftarrow (X) - 1$			$\updownarrow$	$\updownarrow$			INH	5A		3
		$M \leftarrow (M) - 1$							IX1	6A	ff	6
		$M \leftarrow (M) - 1$							IX	7A		5
EOR # <i>opr</i> EOR <i>opr</i> EOR <i>opr</i> EOR <i>opr,X</i> EOR <i>opr,X</i> EOR ,X	EXCLUSIVE OR Accumulator with Memory Byte	$A \leftarrow (A) \oplus (M)$			$\updownarrow$	$\updownarrow$		IMM	A8	ii	2	
								DIR	B8	dd	3	
									EXT	C8	hh ll	4
									IX2	D8	ee ff	5
									IX1	E8	ff	4
							IX	F8		3		

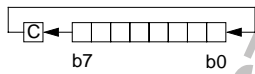
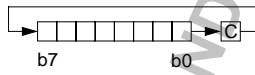
Freescale Semiconductor, Inc.

Table 12-6. Instruction Set Summary (Continued)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles
			H	I	N	Z	C				
INC <i>opr</i> INCA INCX INC <i>opr,X</i> INC ,X	Increment Byte	M ← (M) + 1 A ← (A) + 1 X ← (X) + 1 M ← (M) + 1 M ← (M) + 1	—	—	↑	↑	—	DIR INH INH IX1 IX	3C 4C 5C 6C 7C	dd	5 3 3 6 5
JMP <i>opr</i> JMP <i>opr</i> JMP <i>opr,X</i> JMP <i>opr,X</i> JMP ,X	Unconditional Jump	PC ← Jump Address	—	—	—	—	—	DIR EXT IX2 IX1 IX	C C D C EC FC	dd hh ll ee ff ff	2 3 4 3 2
JSR <i>opr</i> JSR <i>opr</i> JSR <i>opr,X</i> JSR <i>opr,X</i> JSR ,X	Jump to Subroutine	PC ← (PC) + n (n = 1, 2, or 3) Push (PCL); SP ← (SP) - 1 Push (PCH); SP ← (SP) - 1 PC ← Conditional Address	—	—	—	—	—	DIR EXT IX2 IX1 IX	BD C D D D ED FD	dd hh ll ee ff ff	5 6 7 6 5
LDA # <i>opr</i> LDA <i>opr</i> LDA <i>opr</i> LDA <i>opr,X</i> LDA <i>opr,X</i> LDA ,X	Load Accumulator with Memory Byte	A ← (M)	—	—	↑	↑	—	IMM DIR EXT IX2 IX1 IX	A6 B6 C6 D6 E6 F6	ii dd hh ll ee ff ff	2 3 4 5 4 3
LDX # <i>opr</i> LDX <i>opr</i> LDX <i>opr</i> LDX <i>opr,X</i> LDX <i>opr,X</i> LDX ,X	Load Index Register with Memory Byte	X ← (M)	—	—	↑	↑	—	IMM DIR EXT IX2 IX1 IX	AE BE CE DE EE FE	ii dd hh ll ee ff ff	2 3 4 5 4 3
LSL <i>opr</i> LSLA LSLX LSL <i>opr,X</i> LSL ,X	Logical Shift Left (Same as ASL)		—	—	↑	↑	↑	DIR INH INH IX1 IX	38 48 58 68 78	dd	5 3 3 6 5
LSR <i>opr</i> LSRA LSRX LSR <i>opr,X</i> LSR ,X	Logical Shift Right		—	—	0	↑	↑	DIR INH INH IX1 IX	34 44 54 64 74	dd	5 3 3 6 5
MUL	Unsigned Multiply	X : A ← (X) × (A)	0	—	—	—	0	INH	42		11
NEG <i>opr</i> NEGA NEGX NEG <i>opr,X</i> NEG ,X	Negate Byte (Two's Complement)	M ← -(M) = \$00 - (M) A ← -(A) = \$00 - (A) X ← -(X) = \$00 - (X) M ← -(M) = \$00 - (M) M ← -(M) = \$00 - (M)	—	—	↑	↑	↑	DIR INH INH IX1 IX	30 40 50 60 70	ii ff	5 3 3 6 5
NOP	No Operation		—	—	—	—	—	INH	9D		2

INSTRUCTION SET

Table 12-6. Instruction Set Summary (Continued)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles
			H	I	N	Z	C				
ORA #opr ORA opr ORA opr ORA opr,X ORA opr,X ORA ,X	Logical OR Accumulator with Memory	$A \leftarrow (A) \vee (M)$	—	—	↑	↑	—	IMM DIR EXT IX2 IX1 IX	AA BA CA DA EA FA	ii dd hh ll ee ff ff	2 3 4 5 4 3
ROL opr ROLA ROLX ROL opr,X ROL ,X	Rotate Byte Left through Carry Bit		—	—	↑	↑	↑	DIR INH INH IX1 IX	39 49 59 69 79	dd ff	5 3 3 6 5
ROR opr RORA RORX ROR opr,X ROR ,X	Rotate Byte Right through Carry Bit		—	—	↑	↑	↑	DIR INH INH IX1 IX	36 46 56 66 76	dd ff	5 3 3 6 5
RSP	Reset Stack Pointer	$SP \leftarrow \$00FF$	—	—	—	—	—	INH	9C		2
RTI	Return from Interrupt	$SP \leftarrow (SP) + 1$ ; Pull (CCR) $SP \leftarrow (SP) + 1$ ; Pull (A) $SP \leftarrow (SP) + 1$ ; Pull (X) $SP \leftarrow (SP) + 1$ ; Pull (PCH) $SP \leftarrow (SP) + 1$ ; Pull (PCL)	↑	↑	↑	↑	↑	INH	80		6
RTS	Return from Subroutine	$SP \leftarrow (SP) + 1$ ; Pull (PCH) $SP \leftarrow (SP) + 1$ ; Pull (PCL)						INH			
SBC #opr SBC opr SBC opr SBC opr,X SBC opr,X SBC ,X	Subtract Memory Byte and Carry Bit from Accumulator	$A \leftarrow (A) - (M) - (C)$	—	—	↑	↑	↑	IMM DIR EXT IX2 IX1 IX	A2 B2 C2 D2 E2 F2	ii dd hh ll ee ff ff	2 3 4 5 4 3
SEC	Set Carry Bit	$C \leftarrow 1$	—	—	—	—	1	INH	99		2
SEI	Set Interrupt Mask	$I \leftarrow 1$	—	1	—	—	—	INH	9B		2
STA opr STA opr STA opr,X STA opr,X STA ,X	Store Accumulator in Memory	$M \leftarrow (A)$	—	—	↑	↑	—	DIR EXT IX2 IX1 IX	B7 C7 D7 E7 F7	dd hh ll ee ff ff	4 5 6 5 4
STOP	Stop Oscillator and Enable IRQ Pin		—	0	—	—	—	INH	8E		2
STX opr STX opr STX opr,X STX opr,X STX ,X	Store Index Register In Memory	$M \leftarrow (X)$	—	—	↑	↑	—	DIR EXT IX2 IX1 IX	BF CF DF EF FF	dd hh ll ee ff ff	4 5 6 5 4

Freescale Semiconductor, Inc.



Table 12-6. Instruction Set Summary (Continued)

Source Form	Operation	Description	Effect on CCR					Address Mode	Opcode	Operand	Cycles
			H	I	N	Z	C				
SUB #opr SUB opr SUB opr SUB opr,X SUB opr,X SUB ,X	Subtract Memory Byte from Accumulator	$A \leftarrow (A) - (M)$	—	—	↕	↕	↕	IMM DIR EXT IX2 IX1 IX	A0 B0 C0 D0 E0 F0	ii dd hh ll ee ff ff	2 3 4 5 4 3
SWI	Software Interrupt	PC ← (PC) + 1; Push (PCL) SP ← (SP) - 1; Push (PCH) SP ← (SP) - 1; Push (X) SP ← (SP) - 1; Push (A) SP ← (SP) - 1; Push (CCR) SP ← (SP) - 1; I ← 1 PCH ← Interrupt Vector High Byte PCL ← Interrupt Vector Low Byte	—	1	—	—	—	INH	83		10
TAX	Transfer Accumulator to Index Register	$X \leftarrow (A)$	—	—	—	—	—	INH	97		2
TST opr TSTA TSTX TST opr,X TST ,X	Test Memory Byte for Negative or Zero	$(M) - \$00$	—	—	—	—	—	DIR INH INH IX1 IX	3D 4D 5D 6D 7D	dd ff	4 3 3 5 4
TXA	Transfer Index Register to Accumulator	$A \leftarrow (X)$	—	—	—	—	—	INH	9F		2
WAIT	Stop CPU Clock and Enable Interrupts		—	↕	—	—	—	INH	8F		2

- |       |   |      |                                      |
|-------|---|------|--------------------------------------|
| A     | Accumulator   | opr  | Operand (one or two bytes)           |
| C     | Carry/borrow flag   | PC   | Program counter                      |
| CCR   | Condition code register   | PCH  | Program counter high byte            |
| dd    | Direct address of operand   | PCL  | Program counter low byte             |
| dd rr | Direct address of operand and relative offset of branch instruction | REL  | Relative addressing mode             |
| DIR   | Direct addressing mode  | rel  | Relative program counter offset byte |
| ee ff | High and low bytes of offset in indexed, 16-bit offset addressing   | rr   | Relative program counter offset byte |
| EXT   | Extended addressing mode  | SP   | Stack pointer                        |
| ff    | Offset byte in indexed, 8-bit offset addressing                     | X    | Index register                       |
| H     | Half-carry flag   | Z    | Zero flag                            |
| hh ll | High and low bytes of operand address in extended addressing        | #    | Immediate value                      |
| I     | Interrupt mask  | ^    | Logical AND                          |
| ii    | Immediate operand byte  | ∨    | Logical OR                           |
| IMM   | Immediate addressing mode   | ⊕    | Logical EXCLUSIVE OR                 |
| INH   | Inherent addressing mode  | ()   | Contents of                          |
| IX    | Indexed, no offset addressing mode                                  | -( ) | Negation (two's complement)          |
| IX1   | Indexed, 8-bit offset addressing mode                               | ←    | Loaded with                          |
| IX2   | Indexed, 16-bit offset addressing mode                              | ?    | If                                   |
| M     | Memory location   | :    | Concatenated with                    |
| N     | Negative flag   | ↕    | Set or cleared                       |
| n     | Any bit   | —    | Not affected                         |

INSTRUCTION SET

**Table 12-7. Opcode Map**

MSB LSB	Bit Manipulation		Branch			Read-Modify-Write				Control			Register/Memory					MSB LSB
	DIR	DIR	REL	DIR	REL	INH	DIR	INH	IX1	IX	INH	INH	IMM	DIR	EXT	IX2	IX1	
0	5 DIR	5 DIR	2	3	2	3	4	5	6	7	8	9	A	B	C	D	E	F
0	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	5 DIR	3 INH	6 IX1	5 IX	9 INH		2 IMM	3 DIR	4 EXT	5 IX2	4 IX1	3 IX
1	5 DIR	5 DIR	3 REL	3 REL	3 REL								2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
2	5 DIR	5 DIR	3 REL		3 REL	11 INH							2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
3	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	3 COMX	3 COM	6 IX1	5 IX	10 INH		2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
4	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	3 LSRX	3 LSR	6 IX1	5 IX			2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
5	5 DIR	5 DIR	3 REL		3 REL								2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
6	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	3 ROR	3 ROR	6 IX1	5 IX			2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
7	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	3 ASRX	3 ASR	6 IX1	5 IX			2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
8	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	5 ASL/LSL	5 ASL/LSL	6 IX1	5 IX			2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
9	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	3 ROLX	3 ROL	6 IX1	5 IX			2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
A	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	3 DECA	3 DEC	6 IX1	5 IX			2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
B	5 DIR	5 DIR	3 REL		3 REL								2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
C	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	3 INCA	3 INCX	6 IX1	5 IX			2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
D	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	3 TSTA	3 TSTX	5 IX1	4 IX			6 REL	2 DIR	6 EXT	7 IX2	6 IX1	5 IX
E	5 DIR	5 DIR	3 REL		3 REL						2 INH		2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX
F	5 DIR	5 DIR	3 REL	5 DIR	3 REL	3 INH	3 CLRA	3 CLRX	6 IX1	5 IX			2 IMM	2 DIR	4 EXT	5 IX2	4 IX1	3 IX

<p>INH = Inherent IMM = Immediate DIR = Direct EXT = Extended</p>	<p>REL = Relative IX = Indexed, No Offset IX1 = Indexed, 8-Bit Offset IX2 = Indexed, 16-Bit Offset</p>
---	--

<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%; text-align: center;">MSB</td> <td style="width: 50%; text-align: center;">0</td> </tr> <tr> <td style="width: 50%; text-align: center;">LSB</td> <td style="width: 50%; text-align: center;">BRSET0 3</td> </tr> </table> <p style="text-align: center;">MSB of Opcode in Hexadecimal</p>	MSB	0	LSB	BRSET0 3	<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%; text-align: center;">MSB</td> <td style="width: 50%; text-align: center;">0</td> </tr> <tr> <td style="width: 50%; text-align: center;">LSB</td> <td style="width: 50%; text-align: center;">BRSET0 3</td> </tr> </table> <p style="text-align: center;">MSB of Opcode in Hexadecimal</p>	MSB	0	LSB	BRSET0 3
MSB	0								
LSB	BRSET0 3								
MSB	0								
LSB	BRSET0 3								

<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%; text-align: center;">MSB</td> <td style="width: 50%; text-align: center;">0</td> </tr> <tr> <td style="width: 50%; text-align: center;">LSB</td> <td style="width: 50%; text-align: center;">BRSET0 3</td> </tr> </table> <p style="text-align: center;">MSB of Opcode in Hexadecimal</p>	MSB	0	LSB	BRSET0 3	<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%; text-align: center;">MSB</td> <td style="width: 50%; text-align: center;">0</td> </tr> <tr> <td style="width: 50%; text-align: center;">LSB</td> <td style="width: 50%; text-align: center;">BRSET0 3</td> </tr> </table> <p style="text-align: center;">MSB of Opcode in Hexadecimal</p>	MSB	0	LSB	BRSET0 3
MSB	0								
LSB	BRSET0 3								
MSB	0								
LSB	BRSET0 3								

## SECTION 13 ELECTRICAL SPECIFICATIONS

### 13.1 Maximum Ratings

(Voltages referenced to  $V_{SS}$ )

Rating	Symbol	Value	Unit
Supply Voltage	$V_{DD}$	-0.3 to +7.0	V
Input Voltage	$V_{IN}$	$V_{SS} - 0.3$ to $V_{DD} + 0.3$	V
Self-Check Modes (IRQ Pin Only)	$V_{IN}$	$V_{SS} - 0.3$ to $2 \times V_{DD} + 0.3$	V
Current Drain Per Pin Excluding $V_{DD}$ and $V_{SS}$	I	25	mA
Operating Temperature Range 68HC05P9AP (Standard) 68HC05P9ACP (Extended) 68HC05P9AVP (Automotive) 68HC05P9AMP (Automotive)	$T_A$	$T_L$ to $T_H$ 0 to +70 -40 to +85 -40 to +105 -40 to +125	°C
Storage Temperature Range	$T_{stg}$	-65 to +150	°C

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum-rated voltages to this high-impedance circuit. For proper operation, it is recommended that  $V_{in}$  and  $V_{out}$  be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ . Reliability of operation is enhanced if unused inputs are connected to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ).

### 13.2 Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance Plastic DIP Plastic SOIC	$\theta_{JA}$	60 71	°C/W

**13.3 DC Electrical Characteristics**

**Table 13-1. DC Electrical Characteristics (V<sub>DD</sub> = 5 V)**

(V<sub>DD</sub> = 5.0 Vdc ± 10%, V<sub>SS</sub> = 0 Vdc, T<sub>A</sub> = -40°C to +125°C, unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Output Voltage I <sub>LOAD</sub> = 10.0 μA I <sub>LOAD</sub> = -10.0 μA	V <sub>OL</sub> V <sub>OH</sub>	— V <sub>DD</sub> -0.1	— —	0.1 —	V
Output High Voltage (I <sub>LOAD</sub> = -0.8 mA) PA0-PA7, PB5-PB7, PC2-PC7, PD5, TCMP (I <sub>LOAD</sub> = -5.0 mA) PC0-PC1	V <sub>OH</sub> V <sub>OH</sub>	V <sub>DD</sub> -0.8 V <sub>DD</sub> -0.8	— —	— —	V
Output Low Voltage (I <sub>LOAD</sub> = 1.6 mA) PA0-PA7, PB5-PB7, PC2-PC7, PD5, TCMP (I <sub>LOAD</sub> = 15 mA) PC0-PC1	V <sub>OL</sub> V <sub>OL</sub>	— —	— —	0.4 0.4	V
Input High Voltage PA0-PA7, PB5-PB7, PC0-PC7, PD5, TCAP/PD7, IRQ, RESET, OSC1	V <sub>IH</sub>	0.7 × V <sub>DD</sub>	—	V <sub>DD</sub>	V
Input Low Voltage PA0-PA7, PB5-PB7, PC0-PC7, PD5, TCAP/PD7, IRQ, RESET, OSC1	V <sub>IL</sub>	V <sub>SS</sub>	—	0.2 × V <sub>DD</sub>	V
Supply Current Run (A/D Enabled) Wait (A/D Enabled) Wait (A/D Disabled)/Halt Stop 25°C 0°C to +70°C -40°C to +85°C -40°C to +105°C -40°C to +125°C	I <sub>DD</sub>	— — — — — — — — —	3.3 1.7 1.0 2 — — — — —	TBD TBD TBD 5 TBD TBD TBD TBD 100	mA mA mA μA μA μA μA μA
I/O Ports Hi-Z Leakage Current PA0-PA7, PB5-PB7, PC0-PC2, PD5	I <sub>IL</sub>	—	—	± 10	μA
A/D Ports Hi-Z Leakage Current PC3-PC7	I <sub>OZ</sub>	—	—	± 1	μA
Input Current RESET, IRQ, OSC1, TCAP/PD7	I <sub>IN</sub>	—	—	± 1	μA
I/O Ports Switch Resistance (Pullup Enabled PA0-PA7)	R <sub>P7A</sub>	TBD	15	TBD	kΩ
Capacitance Ports (as Input or Output) RESET, IRQ	C <sub>OUT</sub> C <sub>IN</sub>	— —	— —	12 8	pF

NOTES:

1. All values shown reflect average measurements.
2. Typical values at midpoint of voltage range, 25°C.
3. Wait I<sub>DD</sub>: Only timer system active.
4. Run (Operating) I<sub>DD</sub>, Wait I<sub>DD</sub>: Measured using external square wave clock source (f<sub>osc</sub> = 4.2 MHz), all inputs 0.2 V from rail; no dc loads, less than 50 pF on all outputs, C<sub>L</sub> = 20 pF on OSC2.
5. Wait, Stop I<sub>DD</sub>: All ports configured as inputs, V<sub>IL</sub> = 0.2 V, V<sub>IH</sub> = V<sub>DD</sub> - 0.2 V.
6. Wait I<sub>DD</sub> is affected linearly by the OSC2 capacitance.

**Table 13-2. DC Electrical Characteristics ( $V_{DD} = 3.3\text{ V}$ )**  
 ( $V_{DD} = 3.3\text{ Vdc} \pm 10\%$ ,  $V_{SS} = 0\text{ Vdc}$ ,  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ , unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Output Voltage $I_{LOAD} = 10.0\ \mu\text{A}$ $I_{LOAD} = -10.0\ \mu\text{A}$	$V_{OL}$ $V_{OH}$	— $V_{DD}-0.1$	— —	0.1 —	V
Output High Voltage ( $I_{LOAD} = -0.2\text{ mA}$ ) PA0-PA7, PB5-PB7, PC2-PC7, PD5, TCMP ( $I_{LOAD} = -1.5\text{ mA}$ ) PC0-PC1	$V_{OH}$ $V_{OH}$	$V_{DD}-0.3$ $V_{DD}-0.3$	— —	— —	V
Output Low Voltage ( $I_{LOAD} = 0.4\text{ mA}$ ) PA0-PA7, PB5-PB7, PC2-PC7, PD5, TCMP ( $I_{LOAD} = 6.0\text{ mA}$ ) PC0-PC1	$V_{OL}$ $V_{OL}$	— —	— —	0.3 0.3	V
Input High Voltage PA0-PA7, PB5-PB7, PC0-PC7, PD5, TCAP/PD7, IRQ, RESET, OSC1	$V_{IH}$	$0.7 \times V_{DD}$	—	$V_{DD}$	V
Input Low Voltage PA0-PA7, PB5-PB7, PC0-PC7, PD5, TCAP/PD7, IRQ, RESET, OSC1	$V_{IL}$	$V_{SS}$	—	$0.2 \times V_{DD}$	V
Supply Current Run (A/D Enabled) Wait (A/D Enabled) Wait (A/D Disabled)/Halt Stop 25°C 0°C to +70°C -40°C to +85°C -40°C to +105°C -40°C to +125°C	$I_{DD}$	— — — — — — — —	1.2 0.8 0.4 1 — — — —	TBD TBD TBD 3 TBD TBD TBD 70	mA mA mA $\mu\text{A}$ $\mu\text{A}$ $\mu\text{A}$ $\mu\text{A}$ $\mu\text{A}$
I/O Ports Hi-Z Leakage Current PA0-PA7, PB5-PB7, PC0-PC2, PD5	$I_{IL}$	—	—	$\pm 10$	$\mu\text{A}$
A/D Ports Hi-Z Leakage Current PC3-PC7	$I_{OZ}$	—	—	$\pm 1$	$\mu\text{A}$
Input Current RESET, IRQ, OSC1, TCAP/PD7	$I_{IN}$	—	—	$\pm 1$	$\mu\text{A}$
I/O Ports Switch Resistance (Pullup Enabled PA0-PA7)	$R_{PTA}$	TBD	25	TBD	k $\Omega$
Capacitance Ports (as Input or Output) RESET, IRQ	$C_{OUT}$ $C_{IN}$	— —	— —	12 8	pF

NOTES:

1. All values shown reflect average measurements.
2. Typical values at midpoint of voltage range, 25°C.
3. Wait  $I_{DD}$ : Only timer system active.
4. Run (Operating)  $I_{DD}$ , Wait  $I_{DD}$ : Measured using external square wave clock source ( $f_{OSC} = 2.0\text{ MHz}$ ), all inputs 0.2 V from rail; no dc loads, less than 50 pF on all outputs,  $C_L = 20\text{ pF}$  on OSC2.
5. Wait, Stop  $I_{DD}$ : All ports configured as inputs,  $V_{IL} = 0.2\text{ V}$ ,  $V_{IH} = V_{DD} - 0.2\text{ V}$ .
6. Wait  $I_{DD}$  is affected linearly by the OSC2 capacitance.

ELECTRICAL SPECIFICATIONS

**13.4 A/D Converter Characteristics**

**Table 13-3. A/D Converter Characteristics**

Characteristic	Min	Max	Unit
Resolution	8	8	Bit
Absolute Accuracy (4.0 V > V <sub>RH</sub> > V <sub>DD</sub> ) (See Note 1)	—	±1-1/2	LSB
Conversion Range V <sub>RH</sub>	V <sub>SS</sub> V <sub>SS</sub>	V <sub>RH</sub> V <sub>DD</sub>	V
Conversion Time (Includes Sampling Time) External Clock (XTAL) Internal RC Oscillator (ADRC = 1)	32 —	32 32	t <sub>AD</sub> μs
Power-Up Time	—	100	μs
Monotonicity	Inherent (Within Total Error)		
Zero Input Reading (V <sub>in</sub> = 0 V)	00	01	Hex
Full-Scale Reading (V <sub>in</sub> = V <sub>RH</sub> )	FF	FF	Hex
Sample Acquisition Time (see Note 2) External Clock (XTAL) Internal RC Oscillator (ADRC = 1)	12 —	12 12	t <sub>AD</sub> μs
Input Capacitance PC3/AN3-PC6/AN0	—	12	pF
Analog Input Voltage	V <sub>SS</sub>	V <sub>RH</sub>	V
Input Leakage (see Note 4) AN0-AN3 V <sub>RH</sub>	— —	±1 ±1	μA

NOTES:

1. A/D accuracy may decrease proportionately as V<sub>RH</sub> is reduced below 4.0 V.
2. Source impedances greater than 10 kΩ adversely affect internal RC charging time during input sampling.
3. t<sub>AD</sub> = t<sub>cyc</sub> if clock source is MCU.
4. The external system error caused by input leakage current is approximately equal to the product of R source and input current.

Freescale Semiconductor, Inc.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2009

13.5 SIOP Timing

Table 13-4. SIOP Timing ( $V_{DD} = 5\text{ V}$ )

( $V_{DD} = 5.0\text{ Vdc} \pm 10\%$ ,  $V_{SS} = 0\text{ Vdc}$ ,  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ , unless otherwise noted)

Num.	Characteristic	Symbol	Min	Max	Unit
	Operating Frequency Master Slave	$f_{op(m)}$ $f_{op(s)}$	0.25 dc	0.25 0.25	$f_{op}$
1	Cycle Time Master Slave	$t_{cyc(m)}$ $t_{cyc(s)}$	4.0 4.0	4.0 —	$t_{cyc}$
2	Clock (SCK) Low Time	$t_{cyc}$	932	—	ns
3	SDO Data Valid Time	$t_v$	—	200	ns
4	SDO Hold Time	$t_{ho}$	0	—	ns
5	SDI Setup Time	$t_s$	100	—	ns
6	SDI Hold Time	$t_h$	100	—	ns

NOTE:  $f_{op} = 2.1\text{ MHz}$  maximum

Table 13-5. SIOP Timing ( $V_{DD} = 3.3\text{ V}$ )

( $V_{DD} = 3.3\text{ Vdc} \pm 10\%$ ,  $V_{SS} = 0\text{ Vdc}$ ,  $T_A = -40^\circ\text{C}$  to  $+125^\circ\text{C}$ , unless otherwise noted)

Num.	Characteristic	Symbol	Min	Max	Unit
	Operating Frequency Master Slave	$f_{op(m)}$ $f_{op(s)}$	0.25 dc	0.25 0.25	$f_{op}$
1	Cycle Time Master Slave	$t_{cyc(m)}$ $t_{cyc(s)}$	4.0 4.0	4.0 —	$t_{cyc}$
2	Clock (SCK) Low Time	$t_{cyc}$	1980	—	ns
3	SDO Data Valid Time	$t_v$	—	400	ns
4	SDO Hold Time	$t_{ho}$	0	—	ns
5	SDI Setup Time	$t_s$	200	—	ns
6	SDI Hold Time	$t_h$	200	—	ns

NOTE:  $f_{op} = 1.0\text{ MHz}$  maximum

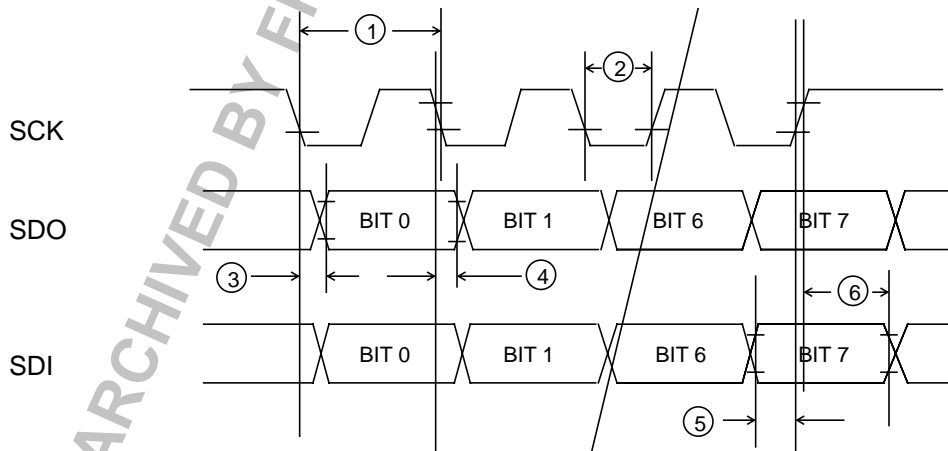


Figure 13-1. SIOP Timing Diagram

**13.6 Control Timing**

**Table 13-6. Control Timing (V<sub>DD</sub> = 5 V)**

(V<sub>DD</sub> = 5.0 Vdc ± 10%, V<sub>SS</sub> = 0 Vdc, T<sub>A</sub> = -40°C to +125°C, unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Frequency of Operation Crystal Option External Clock Option	f <sub>osc</sub>	— dc	4.2 4.2	MHz
Internal Operating Frequency Crystal (f <sub>osc</sub> ÷ 2) External Clock (f <sub>osc</sub> ÷ 2)	f <sub>op</sub>	— dc	2.1 2.1	MHz
Cycle Time	t <sub>cyc</sub>	480	—	ns
Crystal Oscillator Startup Time	t <sub>OXOV</sub>	—	100	ms
Stop Recovery Startup Time (Crystal Oscillator)	t <sub>ILCH</sub>	—	100	ms
RESET Pulse Width	t <sub>RL</sub>	1.5	—	t <sub>cyc</sub>
Interrupt Pulse Width Low (Edge-Triggered)	t <sub>LIH</sub>	125	—	ns
Interrupt Pulse Period	t <sub>LIL</sub>	*	—	t <sub>cyc</sub>
OSC1 Pulse Width	t <sub>OH</sub> , t <sub>OL</sub>	90	—	ns
RC Oscillator Stabilization Time	t <sub>RCON</sub>	—	5	μs
A/D On Current Stabilization Time	t <sub>ADON</sub>	—	100	μs

\*The minimum period t<sub>LIL</sub> should not be less than the number of cycles it takes to execute the interrupt service routine plus 19 t<sub>cyc</sub>.

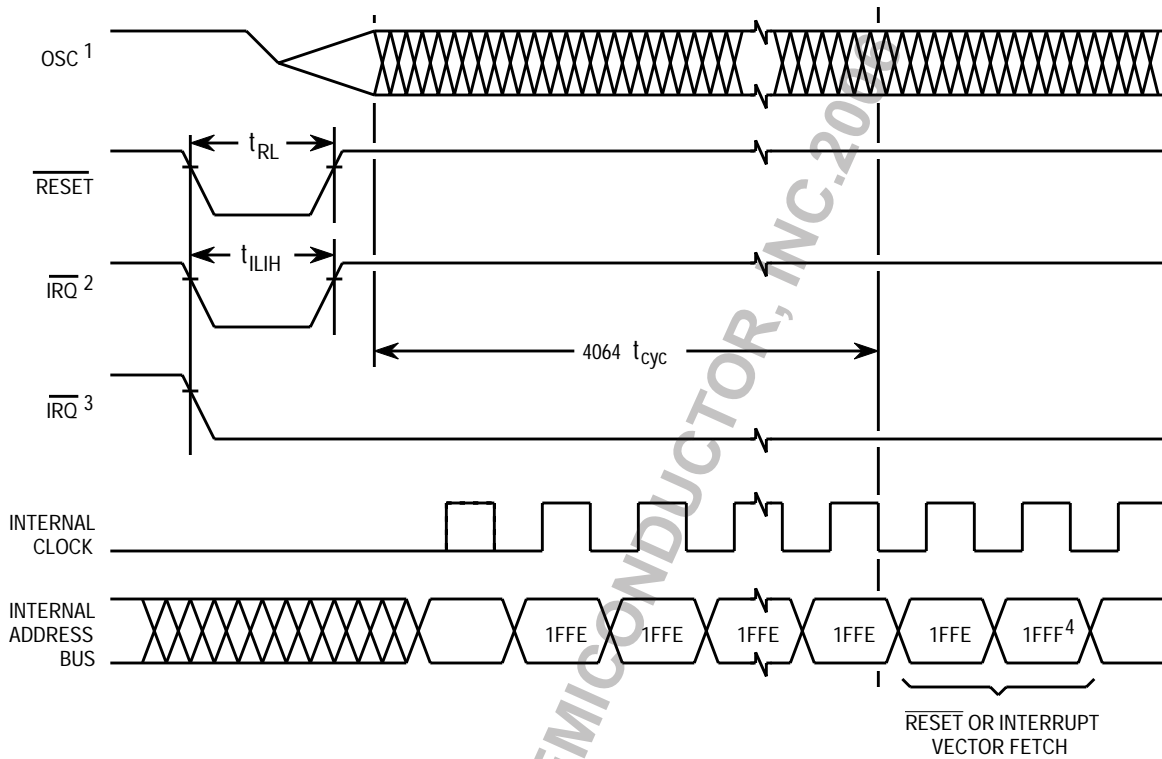
**Table 13-7. Control Timing (V<sub>DD</sub> = 3.3 V)**

(V<sub>DD</sub> = 3.3 Vdc ± 10%, V<sub>SS</sub> = 0 Vdc, T<sub>A</sub> = -40°C to +125°C, unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Frequency of Operation Crystal Option External Clock Option	f <sub>osc</sub>	— dc	2.0 2.0	MHz
Internal Operating Frequency Crystal (f <sub>osc</sub> ÷ 2) External Clock (f <sub>osc</sub> ÷ 2)	f <sub>op</sub>	— dc	1.0 1.0	MHz
Cycle Time	t <sub>cyc</sub>	1000	—	ns
Crystal Oscillator Startup Time	t <sub>OXOV</sub>	—	100	ms
Stop Recovery Startup Time (Crystal Oscillator)	t <sub>ILCH</sub>	—	100	ms
RESET Pulse Width, Excluding Powerup	t <sub>RL</sub>	1.5	—	t <sub>cyc</sub>
Interrupt Pulse Width Low (Edge-Triggered)	t <sub>LIH</sub>	250	—	ns
Interrupt Pulse Period	t <sub>LIL</sub>	*	—	t <sub>cyc</sub>
OSC1 Pulse Width	t <sub>OH</sub> , t <sub>OL</sub>	200	—	ns

\*The minimum period t<sub>LIL</sub> should not be less than the number of cycles it takes to execute the interrupt service routine plus 19 t<sub>cyc</sub>.





NOTES:

1. Represents the internal clocking of the OSC1 pin.
2.  $\overline{\text{IRQ}}$  pin edge-sensitive mask option.
3.  $\overline{\text{IRQ}}$  pin level- and edge-sensitive mask option.
4.  $\overline{\text{RESET}}$  vector address shown for timing example.

Figure 13-2. STOP Recovery Timing

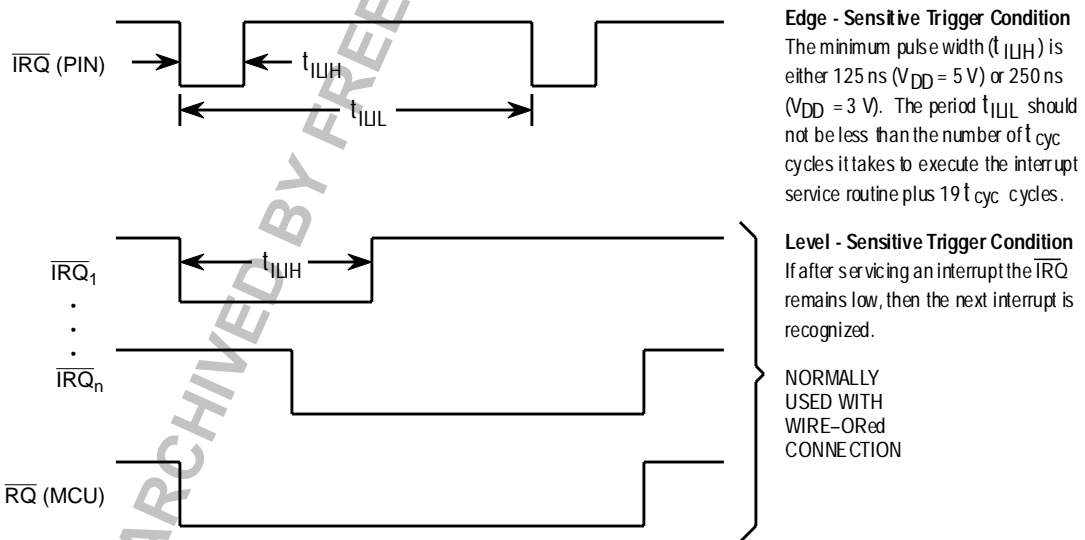


Figure 13-3. External Interrupt Timing

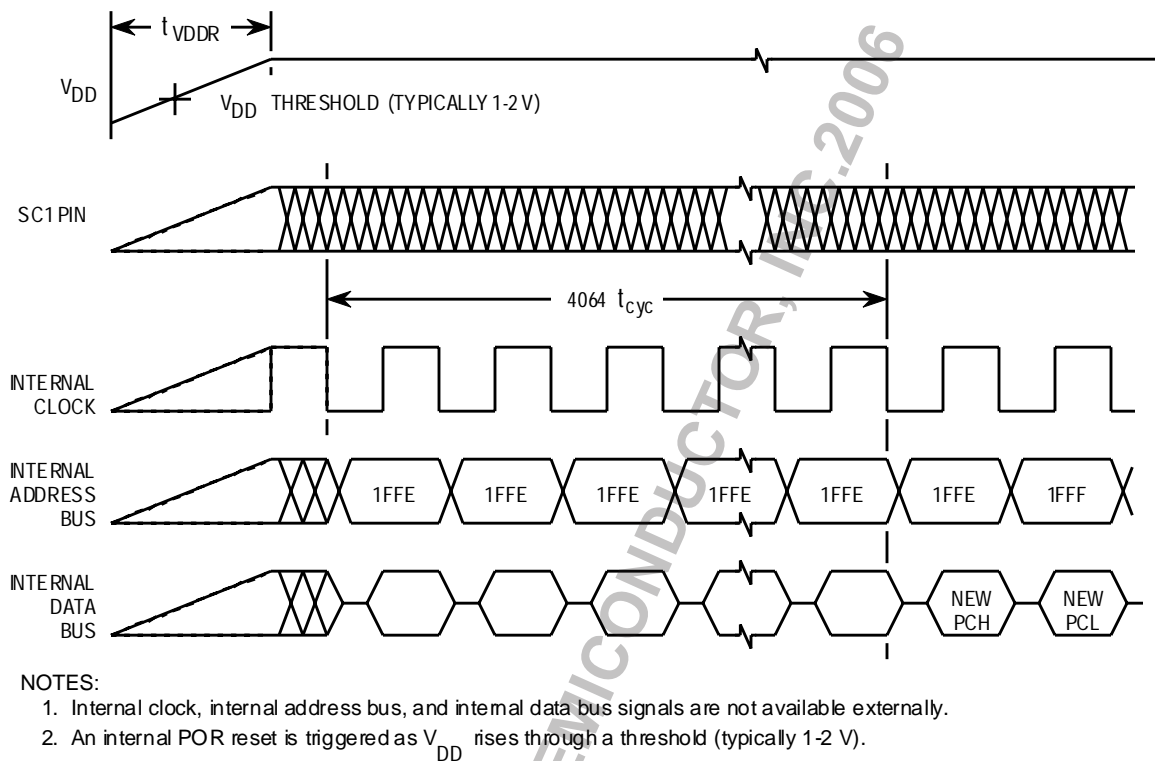


Figure 13-4. Power-On Reset Timing

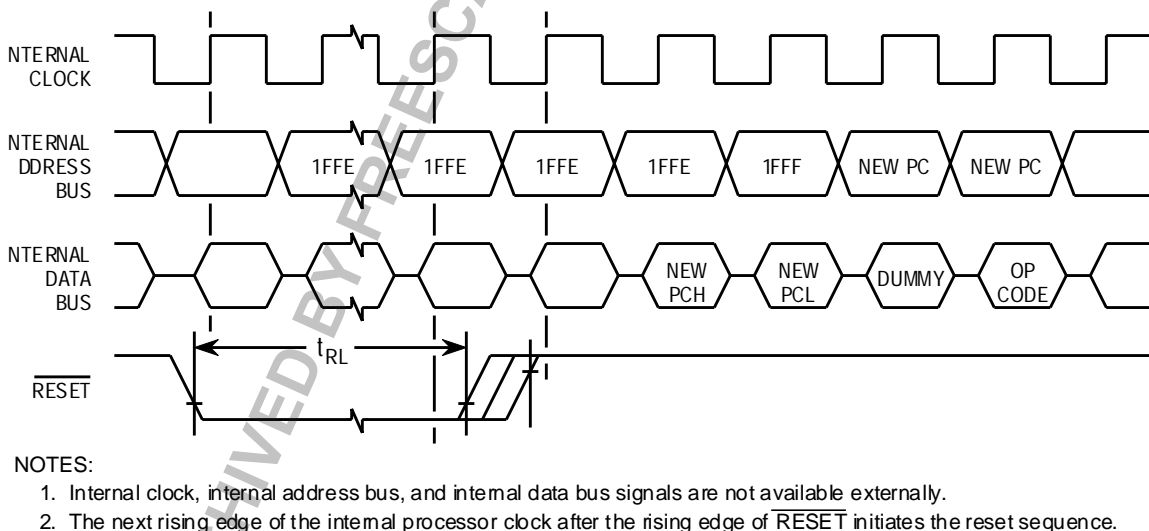
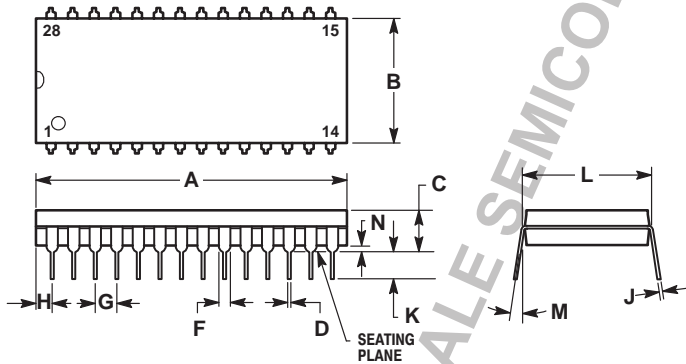


Figure 13-5. External Reset Timing

**SECTION 14  
MECHANICAL SPECIFICATIONS**

This section describes the dimensions of the dual in-line package (DIP) and small outline integrated circuit (SOIC) MCU packages.

**14.1 28-Pin Plastic Dual In-Line Package (Case 710-02)**



NOTES:

1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25mm (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

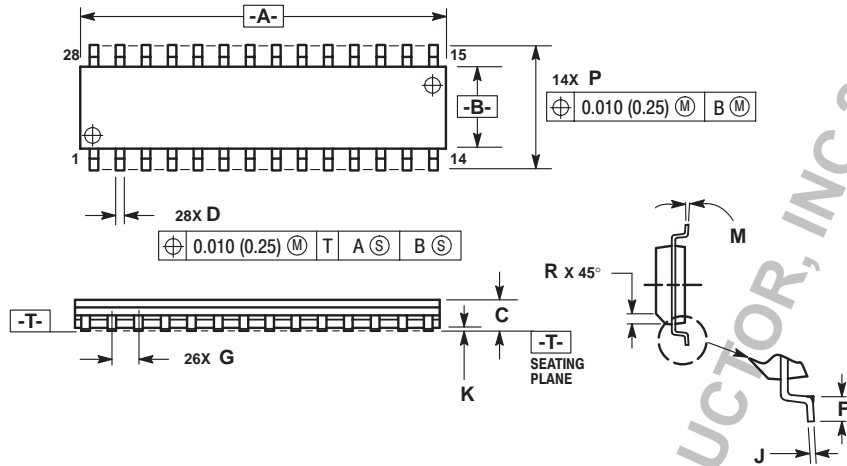
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	36.45	37.21	1.435	1.465
B	13.72	14.22	0.540	0.560
C	3.94	5.08	0.155	0.200
D	0.36	0.56	0.014	0.022
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC.-2006

# Freescale Semiconductor, Inc.

GENERAL RELEASE SPECIFICATION

## 14.2 28-Pin Small Outline Integrated Circuit Package (Case 751F-04)



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	17.80	18.05	0.701	0.711
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

Freescale Semiconductor, Inc.

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

MECHANICAL SPECIFICATIONS

MC68HC0P9A

## SECTION 15 ORDERING INFORMATION

This section contains instructions for ordering custom-masked ROM MCUs.

### 15.1 MCU Ordering Forms

To initiate an order for a ROM-based MCU, first obtain the current ordering form for the MCU from a Motorola representative. Submit the following items when ordering MCUs:

- A current MCU ordering form that is **completely filled out** (Contact your Motorola sales office for assistance.)
- A copy of the customer specification if the customer specification deviates from the Motorola specification for the MCU
- Customer's application program on one of the media listed in **15.2 Application Program Media**

The current MCU ordering form is also available through the Motorola Freeware Bulletin Board Service (BBS). The telephone number is (512) 891-FREE. After making the connection, type `bbs` in lower-case letters. Then press the return key to start the BBS software.

## 15.2 Application Program Media

Please deliver the application program to Motorola in one of the following media:

- Macintosh<sup>®1</sup> 3 1/2-inch diskette (double-sided 800K or double-sided high-density 1.4M)
- MS-DOS<sup>®2</sup> or PC-DOS<sup>™3</sup> 3 1/2-inch diskette (double-sided 720K or double-sided high-density 1.44M)
- MS-DOS<sup>®</sup> or PC-DOS<sup>™</sup> 5 1/4-inch diskette (double-sided double-density 360K or double-sided high-density 1.2M)

Use positive logic for data and addresses.

When submitting the application program on a diskette, clearly label the diskette with the following information:

- Customer name
- Customer part number
- Project or product name
- File name of object code
- Date
- Name of operating system that formatted diskette
- Formatted capacity of diskette

On diskettes, the application program must be in Motorola's S-record format (S1 and S9 records), a character-based object file format generated by M6805 cross assemblers and linkers.

---

### NOTE

Begin the application program at the first user ROM location. Program addresses must correspond exactly to the available on-chip user ROM addresses as shown in the memory map. **Write \$00 in all non-user ROM locations or leave all non-user ROM locations blank.** Refer to the current MCU ordering form for additional requirements. Motorola may request pattern re-submission if non-user areas contain any non-zero code.

---

1. Macintosh is a registered trademark of Apple Computer, Inc.
2. MS-DOS is a registered trademark of Microsoft Corporation.
3. PC-DOS is a trademark of International Business Machines Corporation.

### ORDERING INFORMATION

MC68HC05P9A

If the memory map has two user ROM areas with the same address, then write the two areas in separate files on the diskette. Label the diskette with both file names.

In addition to the object code, a file containing the source code can be included. Motorola keeps this code confidential and uses it only to expedite ROM pattern generation in case of any difficulty with the object code. Label the diskette with the file name of the source code.

### **15.3 ROM Program Verification**

The primary use for the on-chip ROM is to hold the customer's application program. The customer develops and debugs the application program and then submits the MCU order along with the application program.

Motorola inputs the customer's application program code into a computer program that generates a listing verify file. The listing verify file represents the memory map of the MCU. The listing verify file contains the user ROM code and may also contain non-user ROM code, such as self-check code. Motorola sends the customer a computer printout of the listing verify file along with a listing verify form.

To aid the customer in checking the listing verify file, Motorola will program the listing verify file into customer-supplied blank preformatted Macintosh or DOS disks. All original pattern media are filed for contractual purposes and are not returned.

Check the listing verify file thoroughly, then complete and sign the listing verify form and return the listing verify form to Motorola. The signed listing verify form constitutes the contractual agreement for the creation of the custom mask.

### **15.4 ROM Verification Units (RVUs)**

After receiving the signed listing verify form, Motorola manufactures a custom photographic mask. The mask contains the customer's application program and is used to process silicon wafers. The application program cannot be changed after the manufacture of the mask begins. Motorola then produces 10 MCUs, called RVUs, and sends the RVUs to the customer. RVUs are usually packaged in unmarked ceramic and tested to 5 Vdc at room temperature. RVUs are not tested to environmental extremes because their sole purpose is to demonstrate that the customer's user ROM pattern was properly implemented. The 10 RVUs are free of charge with the minimum order quantity. These units are not to be used for qualification or production. RVUs are not guaranteed by Motorola Quality Assurance.

#### **ORDERING INFORMATION**

**Freescale Semiconductor, Inc.**

GENERAL RELEASE SPECIFICATION

**Freescale Semiconductor, Inc.**

ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006



ARCHIVED BY FREESCALE SEMICONDUCTOR, INC. 2006

# Freescale Semiconductor, Inc.

## Home Page:

[www.freescale.com](http://www.freescale.com)

## email:

[support@freescale.com](mailto:support@freescale.com)

## USA/Europe or Locations Not Listed:

Freescale Semiconductor  
Technical Information Center, CH370  
1300 N. Alma School Road  
Chandler, Arizona 85224  
(800) 521-6274  
480-768-2130  
[support@freescale.com](mailto:support@freescale.com)

## Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH  
Technical Information Center  
Schatzbogen 7  
81829 Muenchen, Germany  
+44 1296 380 456 (English)  
+46 8 52200080 (English)  
+49 89 92103 559 (German)  
+33 1 69 35 48 48 (French)  
[support@freescale.com](mailto:support@freescale.com)

## Japan:

Freescale Semiconductor Japan Ltd.  
Headquarters  
ARCO Tower 15F  
1-8-1, Shimo-Meguro, Meguro-ku  
Tokyo 153-0064, Japan  
0120 191014  
+81 2666 8080  
[support.japan@freescale.com](mailto:support.japan@freescale.com)

## Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.  
Technical Information Center  
2 Dai King Street  
Tai Po Industrial Estate,  
Tai Po, N.T., Hong Kong  
+800 2666 8080  
[support.asia@freescale.com](mailto:support.asia@freescale.com)

## For Literature Requests Only:

Freescale Semiconductor  
Literature Distribution Center  
P.O. Box 5405  
Denver, Colorado 80217  
(800) 441-2447  
303-675-2140  
Fax: 303-675-2150  
[LDCForFreescaleSemiconductor@hibbertgroup.com](mailto:LDCForFreescaleSemiconductor@hibbertgroup.com)

RoHS-compliant and/or Pb-free versions of Freescale products have the functionality and electrical characteristics of their non-RoHS-compliant and/or non-Pb-free counterparts. For further information, see <http://www.freescale.com> or contact your Freescale sales representative.

For information on Freescale's Environmental Products program, go to <http://www.freescale.com/epp>.

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document. Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.



Motorola, Inc., 1995

HC05P9AGRS/D

**For More Information On This Product,  
Go to: [www.freescale.com](http://www.freescale.com)**